

# **Gas–solid interface charge tailoring techniques: what we grasped and where to go**

Zhousheng Zhang, Zheming Wang, G. Teyssedre, Tohid Shahsavarian, Mohamadreza Arab Baferani, Geng Chen, Chuanjie Lin, Bo Zhang, Uwe Riechert, Zhipeng Lei, et al.

## **To cite this version:**

Zhousheng Zhang, Zheming Wang, G. Teyssedre, Tohid Shahsavarian, Mohamadreza Arab Baferani, et al.. Gas–solid interface charge tailoring techniques: what we grasped and where to go. Nanotechnology, 2021, 32 (12), pp.122001.  $10.1088/1361-6528/abccea$ . hal-03326097

# **HAL Id: hal-03326097 <https://hal.science/hal-03326097v1>**

Submitted on 25 Aug 2021

**HAL** is a multi-disciplinary open access archive for the deposit and dissemination of scientific research documents, whether they are published or not. The documents may come from teaching and research institutions in France or abroad, or from public or private research centers.

L'archive ouverte pluridisciplinaire **HAL**, est destinée au dépôt et à la diffusion de documents scientifiques de niveau recherche, publiés ou non, émanant des établissements d'enseignement et de recherche français ou étrangers, des laboratoires publics ou privés.

# AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br> **Gas-solid Interface Charge Tailoring Techniques: What**<br>
We Grasped and Where to Go<br>
Zhousheng Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br>
Mohamadr AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br> **Gas-solid Interface Charge Tailoring Techniques: What**<br>
We Grasped and Where to Go<br>
Zhousheng Zhang', Zheming Wang', Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br>
Mohamadreza AUTHOR SUBMITTED MANU<br> **Gas-solid Interface Charge T<br>
<b>We Grasped and Where to G**<br>
Zhousheng Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilber<br>
Mohamadreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>,<br>
Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuany AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.1<br> **Cample 12 (2014)**<br> **Cample 12 (2014)**<br> **Cample Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohip Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanjie Lin<sup>5</sup>, Bo<br>
Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup><br>** *Lin* FED MANUSCRIPT - NANO-127285.R1<br> **rge Tailoring Techniques:**<br> **hetaloring Techniques:**<br> **6 Go**<br> **, Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavaria:**<br>
Chen<sup>4</sup>, Chuanjie Lin<sup>5</sup>, Bo Zhang<sup>6</sup>, Uwe<br>
Chuanyang Li<sup>3\*</sup><br>
of Electric Power, 27285.R1<br> **Techniques: What**<br> **, Tohid Shahsavarian<sup>3</sup>,<br>
n<sup>5</sup>, Bo Zhang<sup>6</sup>, Uwe<br>
Road #2588, Shanghai, 200090,** Gas-solid Interface Charge Tailoring Techniques: What<br>We Grasped and Where to Go<br>Zhousheng Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br>Mohamadreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanjie Lin<sup>5</sup> **Charge Tailoring Technic**<br>
There to Go<br>
Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohid Shat<br>
, Geng Chen<sup>4</sup>, Chuanjie Lin<sup>5</sup>, Bo Zhang<br>
Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup><br>
Miversity of Electric Power, Changyang Road #2588, Shang! **Cailoring Techniques: What**<br>**GO**<br>rt Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br>, Chuanjie Lin<sup>5</sup>, Bo Zhang<sup>6</sup>, Uwe<br>nyang Li<sup>3\*</sup><br>Power, Changyang Road #2588, Shanghai, 200090, **Techniques: What**<br>Tohid Shahsavarian<sup>3</sup>,<br>, Bo Zhang<sup>6</sup>, Uwe<br>ad #2588, Shanghai, 200090, **UES: What**<br>savarian<sup>3</sup>,<br>, Uwe<br>ai, 200090, **)lid Interface Charge Tailor<br>
<b>rasped and Where to Go**<br>
mg Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilbert Teyss<br>
dreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanj<br>
, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang Lit<br>
strical Engineering, Shangh Face Charge Tailoring Techniques: Whold Where to Go<br>
eming Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br>
ferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanjie Lin<sup>5</sup>, Bo Zhang<sup>6</sup>, Uwe<br>
, Yang Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup><br>
hanghai Univer <br>**1828–Solid Interface Charge Tailoring Techniques: What**<br>
21*School of Electrical Engineering, Shanghai University of Electric Power, Changyang Road #2588, Shanghai, 200090,***<br>
21***School of Electrical Engineering, Sha* **Gas-solid Interface Charge Tailoring Techniques: What**<br> **We Grasped and Where to Go**<br>
Zhousheng Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br>
Mohamadreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanjie

Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup> *Laplace, Paul Sabatier University, and Where to Go***<br>** *2***<b>Laplace, Paul Sabatier Sabatier Sabatier School of Electrical Engineering, Shanghai University of Electric Power, Changyang Road #2588<br>** *2Laplace, Paul Sabati* **27 Insulation Research Center, Institute of Material Insulation Research Center, Institute Proposed Research Center, Chuanyang Li<sup>3\*</sup><br><b>32**<br>**Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup><br><sup>1</sup>School of Electric Zhousheng Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilbert<br>
Mohamadreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, C<br>
Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanya<br>
<sup>1</sup>School of Electrical Engineering, Shanghai University of Electric Pov<br>
<sup>2**</sup> **Zhousheng Zhang<sup>1</sup>, Zheming Wang<sup>1</sup>, Gilbert Teyssedre<sup>2</sup>, Tohid Shahsavarian<sup>3</sup>,<br><b>Mohamadreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanjie Lin<sup>5</sup>, Bo Zhang<sup>6</sup>, Uwe<br>Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup><br> Mohamadreza Arab Baferani<sup>3</sup>, Geng Chen<sup>4</sup>, Chuanding Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang** *Shool of Electrical Engineering, Shanghai University of Electric Power, C**People's Republic of China***<br><sup>2</sup>***Lapla* 

*People's Republic of China*<br>*People's Republic Research Center, Institute of Material Connecticut, Storrs 7*<sup>*2</sup>Aaplace, Paul Sabatier University, and CNRS, Toulouse, France*<br><sup>3</sup>*Aaplace, Paul Sabatier University, and CNRS, Toulouse, France*<br><sup>3</sup>*AEectrical Insulation Research Center, Institute of Materials Science, Electric</sup>* <sup>3</sup>Electrical Insulation Research Center, Institute of Materials Science, Electrical and Computer Engineer<br>
Connecticut, Storrs, CT 06269, USA<br>
<sup>4</sup>Beijing Area Major Laboratory of High Voltage and Electromagnetic Compatibi

*Riechert<sup>7</sup>, Zhipeng Lei<sup>8</sup>, Yang Cao<sup>3\*</sup>, Chuanyang Li<sup>3\*</sup><br><sup><i>5*</sup>*School of Electrical Engineering, Shanghai University of Electric Power, Changyang Road #2588, Shanghai, 200090,<br><i>People's Republic of China*<br>*<sup>2</sup>Laplace* <sup>1</sup>School of Electrical Engineering, Shanghai University of Electric Power, Changyang Road #2588, Shanghai, 200090,<br> *People's Republic of China*<br>
<sup>2</sup>*Laplace, Paul Sabatier University, and CNRS, Toulouse, France<br>
<i>Claneti* -Laplace,Paul Saballer University, and CNKS, Lollouse, France<br>"Electrical Insulation Research Center, Institute of Materials Science, Electrical and Computer Engineering, University of<br>"Connecticut, Storrs, CT 06269, USA<br>

Connecticut, Storrs, CT 06269, USA<br>
"Beijing Area Major Laboratory of High Voltage and Electromagnetic Compatibility, North China Electric Power University<br>
Beijing 102206, People's Republic of China<br>
"State Key Laboratory *Abstract:* Charging *Area Mayor Laboratory of Interior Charging and Liectronagnetic Compatibiuty, North China Electric Power University, People's Republic of China<br>
<i>Abstract Key Laboratory of Power Systems, Department of* State Key Laboratory of Power Systems, Department of Electrical Engineering, Tsinghua University, Beijing, 100084,<br>People's Republic of China<br>Shanxi Key Laboratory of Electrical Insulation and Power Equipment, Xi'an Jiaoto *People's Republic of China*<br>
<sup>S</sup>State Key Laboratory of Electrical Insulation and Power Equipment, Xi'an Jiaotong University,Xi'an 710049, China<br>
<sup>7</sup>ABB Switzerland Ltd, High Voltage Products, Zurich, Switzerland<br>
<sup>8</sup>Shan State Key Laboratory of Electrical Insulation and Power Equipment, Xi'an Jiaotong University,Xi'an 710049, China<br>
7ABB Switzerland Ltd, High Voltage Products, Zurich, Switzerland<br>
8Hamxi Key Laboratory of Mining Electrical *ABB* Switzerland Ltd, High Voltage Products, Zurich, Switzerland<br>
<sup>8</sup>Shanxi Key Laboratory of Mining Electrical Equipment and Intelligent Control, College of Electrical and Power<br> **Propineering**, Taiyuan University of Tec Shanxi Key Laboratory of Mining Electrical Equipment and Intelligent Control, College of Electrical and Power<br>Engineering, Taiyuan University of Technology, Taiyuan 030024, China<br>
\*Corresponding authors: <u>yang.cao@uconn.e</u> Engineering, ratyaan onversity of rechnology, ratyaan 050024, china<br>
\*Corresponding authors: <u>yang.cao@uconn.edu;</u> lichuanyangsuper@16<br>
Abstract: Charging of insulators modifies local electric field distribute<br>
the gas ins Contesponaling attators. <u>Fang caonglacomiticant</u>, <u>inchuring supplementation</u> and increases potential threat to the safety of the gas insulated equipment. In this paper, surface charge tailoring techniques are classified Abstract: Charging of insulators modifies loothe gas insulated equipment. In this paper, sur a Dam-flood model. Technical solutions of di of potential solutions to suppress charge accum This paper serves as a guide handboo Im-Hood model. I echnical solutions of different charge tailoring methods are compared and discussed. The outlook<br>otential solutions to suppress charge accumulation is recommended and discussed based on industrial consider

This paper serves as a guide handbook for engineers and researchers into the study of charge tailoring methods.<br>Meanwhile, we hope that the content of this paper could shed some lights upon charge-free insulators to promot Meanwhile, we hope that the content of this paper could shed some lights upon charge-free insulators to promote the<br>industrial application of HVDC GIL/GIS.<br>**Keywords:** Epoxy resins; direct fluorination; surface charge migr surface charge conduction rate fluorination; surface charge migration; DC surface flashover; HVDC GIL.<br> **1. Introduction**<br>
Surface charge accumulation at the surface of insulators inside the HVDC GIL results in electric fi

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 2 of 54<br>
characterization techniques [3] as well as charge tailoring methods begin to draw worldwide attentions.<br>
Efforts have been paid to control these charges, in which AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 2 of 54<br>
characterization techniques [3] as well as charge tailoring methods begin to draw worldwide attentions.<br>
Efforts have been paid to control these charges, in which AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
characterization techniques [3] as well as charge tailoring methods begin to draw worldwide a<br>
Efforts have been paid to control these charges, in which the implementation of n AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 2 of 54<br>acterization techniques [3] as well as charge tailoring methods begin to draw worldwide attentions.<br>Ints have been paid to control these charges, in which the imple

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 2 of 54<br>
characterization techniques [3] as well as charge tailoring methods begin to draw worldwide attentions.<br>
Efforts have been paid to control these charges, in which characterization techniques [3] as well as charge tailoring methods begin to draw worldwide attentions.<br>
Efforts have been paid to control these charges, in which the implementation of nano coatings and fillers<br>
played ver characterization techniques [3] as well as charge tailoring methods begin to draw worldwide attentions.<br>
Efforts have been paid to control these charges, in which the implementation of nano coatings and fillers<br>
played ver Efforts have been paid to control these charges, in which the implementation of nano coatings and fillers<br>played very important role in dielectric property enhancement [4-10].<br>Nanodielectrics attract more attentions in re played very important role in dielectric property enhancement [4-10].<br>
Nanodielectrics attract more attentions in recent years. The DC conductivity of polyaniline was found<br>
increased by doping with TiO<sub>2</sub> nano-fillers, an Nanodielectrics attract more attentions in recent years. The DC conductivity of polyaniline was found<br>increased by doping with TiO<sub>2</sub> nano-fillers, and a very large dielectric constant of about 3700 at room<br>temperature was increased by doping with TiO<sub>2</sub> nano-fillers, and a very large dielectric constant of about 3700 at room<br>temperature was observed [4]. According to literature 5, a consistency between predictions and impedance<br>measurements temperature was observed [4]. According to literature 5, a consistency between predictions and impedance<br>measurements verifies the impact of atomic coordination-number imperfection on the dielectric performance<br>of nanometr measurements verifies the impact of atomic co<br>of nanometric semiconductors. The effectiven<br>decrease in surface charge accumulation and a<br>from literature 9 again verified that an ordered a<br>as a useful way to decay surface c In a strategy and the urgent conductors. The effectiveness of nano-fillers is also verified in literature 7 and 8 that a case in surface charge accumulation and an increase in surface flashover voltage were obtained. Resul decrease in surface charge accumulation and an increase in surface flashover voltage were obtained. Results<br>from literature 9 again verified that an ordered and nonlinear nano coating introduced on epoxy surface serves<br>as

from literature 9 again verified that an ordered and nonlinear nano coating introduced on epoxy surface serves<br>as a useful way to decay surface charges and increase surface flashover voltage. A surface treatment creating a as a useful way to decay surface charges and increase surface flashover voltage. A surface treatment creating a<br>hano surface layer by DBD plasma also decays surface charge effectively when using silicone rubber as a base<br>m nano surface layer by DBD plasma also decays surface charge effectively when using silicone rubber<br>material [10].<br>In recent years, due to the urgent requirement of HVDC GIL driven by the expansion of HVDC<br>especially offsho erial [10].<br>In recent years, due to the urgent requirement of HVDC GIL driven by the expansion of HVDC projects,<br>cicially offshore projects, the problem of surface charge accumulation has become tremendously<br>nounced [11-14 In recent years, due to the urgent requirement of HVDC GIL driven by the expansion of HVDC projects,<br>especially offshore projects, the problem of surface charge accumulation has become tremendously<br>pronounced [11-14]. As a

especially offshore projects, the problem of surface charge accumulation has become tremendously<br>pronounced [11-14]. As a consequence, extensive research studies regarding surface charge behavior has<br>become a focus which i pronounced [11-14]. As a consequence, extensive research studies regarding surface charge behavior has become a focus which is a specific challenge [7-10]. However, suitable surface charge tailoring methods still remain to become a focus which is a specific challenge [7-10]. However, suitable surface charge tailoring methods still<br>remain to be a difficult problem which captures the interests of researchers.<br>It has been accepted that the surf remain to be a difficult problem which captures the interests of researchers.<br>It has been accepted that the surface charge is either from the conducting current from the volume/surface,<br>or due to charge transport along the It has been accepted that the surface charge is either from the conducting current from the volume/surface,<br>or due to charge transport along the direction of electric field lines in the gas phase [15]. Meanwhile, it has<br>be or due to charge transport along the direction of electric field lines in the gas phase [15]. Meanwhile, it has<br>been indicated that due to the differences in local electric field stress, dominant charge types at different<br> been indicated that due to the differences in local electric field stress, dominant charge types at different<br>positions of the insulator are field-dependent, as shown in Figure 1 [16]. Surface flashover at DC voltage has<br>b

specific insulation-electrode arrangement. Bearing in mind this we can further consider suitable manners targeting the decay of these charges. AUTHOR SUBMITTED MANUSCRIPT - NA<br>specific insulation-electrode arrangement. Bearing in mind this<br>targeting the decay of these charges.<br> $C_{\text{HeP}}$ 



**In this paper, to help the reader identify the source of the charge at the gas-solid interface, which is very<br>
Let the reader the** *Instead Company* **at the** *Final hyperion**i**Insection from volume***<br>
<b>IF \frac{1}{R \text{ factor } Gat} Example 1.** Field-dependent model of dominant charge behavior. Unclear factors represents electrostatic charges, Figure 1. Field-dependent model of dominant charge behavior. Unclear factors represents electrostatic charg **Figure 1.** Field-dependent model of dominant charge behavior. Unclear factors represents electrostatic charges, bulk charges, charges from cosmic or PDs, and polarization in the volume, etc.; trapping from gas represents bulk charges, charges from cosmic or PDs, and polarization in the volume, etc.; trapping from gas represents enhanced<br>gas ionization following Townsend's law; injection from volume represents charges injected from volume; C<sub>Ita</sub>P stand for surface potential, hetero-polar charge and homo-polar charge [16].<br>In this paper, to help the reader identify the source of the charge at the gas-solid interface, which is very<br>important while usually be In this paper, to help the reader identify the source of the charge at the gas-solid interface, which is very<br>important while usually be neglected, and the suppression methods more intuitively, we introduce a Dam<br>model to In this paper, to help the reader identify the source of the charge at the gas-solid interface, which is very<br>important while usually be neglected, and the suppression methods more intuitively, we introduce a Dam<br>model to Important while usually be neglected, and the supprobal to explain interestingly how gas-solid in corresponding charge tailoring methods are reviews suppress charge accumulation is recommended and cost this paper can be us







The mean of the destruction/degradation of the forest over years, while some types of floods center field and the product over the destruction of the forest over years, while some types of floods can be developed over a<br>fe Fredging Compendensive continuous heavy rain drop. Nonlinear particles, non-linear continuous heaven to continuous heavy controlling and decay controlling and decaying charges accumulation on the insulator of decaying char Comprehensive Initiatively<br>
management decaying charges doping with nonlinear materials<br>
decaying charges doping with nonlinear materials<br>
Property<br>
Caussing heavy casualties, the flood to houses and populations is equival causing heavy casualties, the flood to houses and populations is equivalent to the charge triggered surface<br>flashover to gas insulated electric power systems. The triggering process for floods can be slow which is due<br>to t Causing heavy casualties, the flood to houses and populations is equivalent to the charge triggered surface<br>flashover to gas insulated electric power systems. The triggering process for floods can be slow which is due<br>to t flashover to gas insulated electric power systems. The triggering process for floods can be slow which is due<br>to the destruction/degradation of the forest over years, while some types of floods can be developed over a<br>few ne destruction/degradation of the forest over years, while some types of floods can be developed over a days due to continuous heavy rain drop. Correspondingly, surface charge accumulation on the insulator be a very slow p few days due to continuous heavy rain drop. Correspondingly, surface charge accumulation on the insulator<br>can be a very slow process due to numerous discrete processes on smallest scale, e.g. charge<br>injection/extraction at

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
construction of a dam can be divided into four aspects: *Flood spilling*, *dam strengthening*, *dredging* and<br> *comprehensive management*, which corresponds to different charge *construction* of a dam can be divided into four aspects: *Flood spilling, dam strengthening, dredging* and *comprehensive management*, which corresponds to different charge tailoring orientations, as shown in Table 1 and AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
construction of a dam can be divided into four aspects: *Flood spilling, dam strengthening, dredging* and<br> *comprehensive management*, which corresponds to different charge tai AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
construction of a dam can be divided into four aspects: *Flood spilling, dam strengthening, dredging* and<br> *comprehensive management,* which corresponds to different charge tai AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
construction of a dam can be divided into four aspects: *Flood spilling, dam strengthening, dredging* and<br> *comprehensive management*, which corresponds to different charge tai construction of a dam can be divided into four aspects: *Flood spilling*, *dam strengthening*, *dredging* and *comprehensive management*, which corresponds to different charge tailoring orientations, as shown in Table 1 an construction of a dam can be divided into four aspects: *Flood spilling, dam strengthening, dredging* and *comprehensive management,* which corresponds to different charge tailoring orientations, as shown in Table 1 and Fi *comprehensive management*, which corresponds to different charge tailoring orientations, as shown in Table 1 and Figure 2. To be more specific, in case when the upstream water level rises, spilling prevents flooding in a and Figure 2. To be more specific, in case when the upstream water level rises, spilling prevents flooding in a<br>manner of keeping water flowing downstream, which is equivalent to increase the surface charge decay rate to<br>h manner of keeping water flowing downstream, which is equivalent to increase the surface charge decay rate to have a lower amount of surface charges; By *dam reinforcement*, the dam becomes stronger so that the water pressu have a lower amount of surface charges; By *dam reinforcement*, the dam becomes stronger so that the water<br>pressure does not endanger the safety of the dam, which is equivalent to increasing the inception electric field<br>fo pressure does not endanger the safety of the dam, which is equivalent to increasing the inception electric field<br>for charge injection so as to suppress injected homo-polar charges; *Dredging* is a commonly used approach to for charge injection so as to suppress injected homo-polar charges; *Dredging* is a commonly used approach to increase the canal depth and therefore increase the capacity of canals for carrying water/floods. Regarding the increase the canal depth and therefore increase the capacity of canals for carrying water/floods. Regacharge tailoring solution, by means of material modification and shape improvement, local electric be optimized and the charge tanoring solution, by means of material modification and shape improvement be optimized and the withstand voltage of the spacer can thereby be increased; Basediments can be dredged and saved for farmlands and the fl ments can be dredged and saved for farmlands and the flood can be prevented. Such *comprehensive*<br>agement methods have the synergistic effect to control surface charges of insulators, i.e. to control the<br>tion of charges an

management methods have the synergistic effect to control surface charges of insulators, i.e. to control the<br>position of charges and initiatively decay these charges. The Dam model constituents and the corresponding<br>surfac position of charges and initiatively decay these charges. The Dam model constituents and the corresponding<br>surface charge tailoring techniques can also be found in Table 1.<br>3 Flood-spilling-increasing surface charge decay<br> surface charge tailoring techniques can also be found in Table 1.<br>3 Flood-spilling-increasing surface charge decay<br>Given the idea of *Flood spilling*, a more conductive surface with higher surface decay rate is obtained.<br>C 3 Flood-spilling-increasing surface charge decay<br>Given the idea of *Flood spilling*, a more conductive surface with higher surface decay rate is obtained.<br>Capability of fluorination, plasma treatment, surface coatings, gam Given the idea of *Flood spilling*, a more condu<br>Capability of fluorination, plasma treatment, surface<br>etc., have been verified in increasing the surface con<br>37, 45, 47, 49]. This chapter firstly reviews the resul<br>analysis ability of fluorination, plasma treatment, surface coatings, gamma ray irradiation, and ozone treatment,<br>have been verified in increasing the surface conductivity and surface charge decay by researchers [30, 33,<br>45, 47, 49 etc., have been verified in increasing the surface conductivity and surface charge decay by researchers [30, 33, 37, 45, 47, 49]. This chapter firstly reviews the results from the above mentioned methods, and a comparative

27, 45, 47, 49].This chapter firstly reviews the results from the above mentioned methods, and a comparative<br>analysis among the research characteristics from each research group is presented.<br>
3.1. Surface fluorination<br>
Su Surface fluorination<br>Surface fluorination<br>Surface fluorination<br>Surface fluorination<br>discussed in Tongingham and the interaction<br>ace. A stable C-F surface layer with different byproducts can be f<br>be controlled [24] and a fl

In 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin<br>They used an  $F_2 / N_2$  mixture with a volume of 12.5%  $F_2$  to fluorinate the epoxy resin sheet with a<br>kness of 0.5 AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 6 of 54<br>In 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin<br>[20]. They used an F<sub>2</sub> / N<sub>2</sub> mixture with a volume of 1 AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 6 of 54<br>In 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin<br>[20]. They used an F<sub>2</sub> / N<sub>2</sub> mixture with a volume of 1 8.7 at all 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin [20]. They used an F<sub>2</sub> / N<sub>2</sub> mixture with a volume of 12.5% F<sub>2</sub> to fluorinate the epoxy resin sheet with AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 6 of 54<br>In 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin<br>[20]. They used an  $F_2 / N_2$  mixture with a volume of 12. In 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin [20]. They used an  $F_2 / N_2$  mixture with a volume of 12.5%  $F_2$  to fluorinate the epoxy resin sheet with a thickn In 2011, Z. An *et al.* conducted pioneering researches on surface fluorination treatments on epoxy resin [20]. They used an  $F_2 / N_2$  mixture with a volume of 12.5%  $F_2$  to fluorinate the epoxy resin sheet with a thickn [20]. They used an  $F_2 / N_2$  mixture with a volume of 12.5%  $F_2$  to fluorinate the epoxy resin sheet with a thickness of 0.55 mm, and the results showed that the surface conductivity was increased from  $1.1 \times 10^{-17}$  S t thickness of 0.55 mm, and the results showed that the surface conductivity was increased from  $1.1 \times 10^{17}$  S to 8.7  $\times 10^{-14}$  S, with a value increasing by 3 orders of magnitude. They believed that the decrease of sur  $8.7 \times 10^{-14}$  S, with a value increasing by 3 orders of magnitude. They belie<br>depth and the adsorption of water on the surface in the vicinity of air an<br>increase of surface conductivity. Based on their preliminary result If and the austropion of water on the surface in the victiny of an afte the main reasons responsible rot<br>asse of surface conductivity. Based on their preliminary results, they modified epoxy sheet to suppress the<br>multation Increase or surface conductivity. Based on their premimiary results, they modified epoxy sheet to suppress the<br>accumulation of surface charges effectively by introducing a surface with lower conductivity through the<br>fluori

Example, and the metrical sample, and the surface conductivity increases with over enductivity intough the fluorination on the insulator surface, they further studied the effect of temperature and fluorination duration on Internation[19]. In otter to further understand the mechanism of the suppression of the change accumulation<br>on the insulator surface, they further studied the effect of temperature and fluorination duration on electrical<br>p on the institutor surface, they further studied the effect of temperature and<br>properties of epoxy based materials [21].<br>Figure 3 shows the surface conductivities of the epoxy before and after<br>that the surface conductivity Figure 3 shows the surface conductivities of the epoxy before and after fluorination. The results showed<br>the surface conductivity of the fluorinated sample at various humidity levels is significantly higher than<br>untreated Figure 3 shows the surface conductivities of the epoxy before and after humidiaton. The festures showed<br>that the surface conductivity of the fluorinated sample at various humidity levels is significantly higher than<br>the u





Figure 4. Surface conductivity at different RH levels for the untreated and surface fluorinated samples for<br>times of 10, 20 and 30min [22].<br>fluorinated samples at different relative humidity levels. The results show that

They concluded that temperature and fluorination time duration 1881. In subsequent researches, they concluded that temperature and fluorination time duration are two important factors controlling the time time duration im **Figure 4.** Surface conductivity at different RH levels for the untreated and surface fluorinated samples for times of 10, 20 and 30min [22].<br>
fluorinated samples at different relative humidity levels. The results show tha Figure 4. Surface conductivity at different RH levels for the untreated and surface fluorinated samples for times of 10, 20 and 30min [22].<br>fluorinated samples at different relative humidity levels. The results show that a times of 10, 20 and 30min [22].<br>
fluorinated samples at different relative humidity levels. The results show that as the fluorination time<br>
duration increases, the surface conductivity increases, while this trend is opposi fluorinated samples at different relative humidity duration increases, the surface conductivity increases,<br>They concluded that temperature and fluorination<br>fluorination process and the surface conductivity,<br>conductivity is They concluded that temperature and fluorination time duration are two<br>
rination process and the surface conductivity, noting that the effect<br>
ductivity is more significant than that of the fluorination time duration [18] rination process and the surface conductivity, noting that the effect of temperature on the surface<br>ductivity is more significant than that of the fluorination time duration [18]. In subsequent researches, they<br>stigated th

conductivity is more significant than that of the fluorination time duration [18]. In subsequent researches, they<br>investigated the discharge characteristics and AC/ DC flashover performance of surface fluorinated epoxy<br>ins investigated the discharge characteristics and AC/ DC flashover performance of surface fluorinated epoxy<br>insulators [23, 36].<br>3.1.2. Researches in University of Southampton<br>G. Chen *et al.* employed the same fluorination t insulators [23, 36].<br>
3.1.2. Researches in University of Southampton<br>
G. Chen *et al.* employed the same fluorination treatment method on the epoxy films [27-29]. Compared<br>
with Z. An's work, G. Chen's research paid more 3.1.2. Researches in University of Southampton<br>G. Chen *et al.* employed the same fluorination treatment method on the epoxy films [27-29]. Compared<br>with Z. An's work, G. Chen's research paid more attention on the breakdo 3.1.2. Researcies in oniversity of southampton<br>
G. Chen *et al.* employed the same fluorination treatment method on the epoxy films [27-29]. Compared<br>
with Z. An's work, G. Chen's research paid more attention on the break G. Chen *et al.* employed the same fluorination treatment method on the epoxy f with Z. An's work, G. Chen's research paid more attention on the breakdown prop found that with the prolongation of the fluorination time dur



believed that the increase in the surface conductivity may not be due to the fluorine layer itself, but because of the moisture absorbed by the surface conductivity may not be due to the fluorine layer itself, but because Figure 5. DC conductivity measurement for 250µm epoxy resin sample being treated after different fluorination time [29].<br>
In their subsequent studies, they paid more attention to the charge suppressing mechanism [25]. They Figure 5. DC conductivity measurement for  $250\mu m$  epoxy resin sample being treated after different fluorination time [29].<br>In their subsequent studies, they paid more attention to the charge suppressing mechanism [25]. T Figure 5. DC conductivity measurement for 250µm epoxy resin sample being treated after different fluorination time [29].<br>In their subsequent studies, they paid more attention to the charge suppressing mechanism [25]. They fluorination time [29].<br>In their subsequent studies, they paid more attention to the charge suppressing mechand<br>believed that the increase in the surface conductivity may not be due to the fluorine layer itself<br>the moistur In their stosequent statues, they paid into attention to the charge eved that the increase in the surface conductivity may not be due to moisture absorbed by the surface layer [26]. It is interesting to not ductivity of t moisture absorbed by the surface layer [26]. It is interesting to note that according to a recent report, the<br>ductivity of the fluorinated layer has a negative correlation with increase of the temperature [15], while the<br>l

conductivity of the fluorinated layer has a negative correlation with increase of the temperature [15], while the<br>result provided by G.Chen implies that increase of the conductivity by fluorination process is due to absorb result provided by G.Chen implies that increase of the conductivity by fluorination process is due to absorbed<br>surface moisture, which can be the rationale behind this phenomenon.<br>3.1.3. Researches in Tianjin University<br>B. surface moisture, which can be the rationale behind this phenomenon.<br>
3.1.3. Researches in Tianjin University<br>
B. Du *et al.* Studied the surface charge decay property of fluorinated epoxy samples [30]. The surface<br>
flash 3.1.3. Researches in Tianjin University<br>B. Du *et al.* Studied the surface charge decay property of fluorinated epoxy samples [30]. The surface<br>flashover voltage of samples with different fluorination time durations are e **B.** Du *et al.* Studied the surface charge decay property of fluorinated epoxy samples [30]. The surface flashover voltage of samples with different fluorination time durations are evaluated. They introduced the carrier B. Du *et al.* Studied the surface charge decay property flashover voltage of samples with different fluorination tin carrier mobility and trap distributions to analyze the effect flashover characteristics [30]. Furthermo



Figure 6. Insulators with interfacial  $\sigma$ -FGM: a four-gradient tapered insulator (F-45-30-15-0) [31].<br>
Figure 6. Insulators with interfacial  $\sigma$ -FGM: a four-gradient tapered insulator (F-45-30-15-0) [31].<br>
3.1.4. Resear Figure 6. Insulators with interfacial  $\sigma$ -FGM: a four-gradient tapered insulator (F-45-30-15-0) [31].<br>
3.1.4. Researches in Tsinghua University<br>
Following Z. An 's pioneering research regarding fluorination of epoxy resi Figure 6. Insulators with interfacial  $\sigma$ -FGM: a four-gradient tapered insulator (F-45-30-15-0) [31].<br>3.1.4. Researches in Tsinghua University<br>Following Z. An 's pioneering research regarding fluorination of epoxy resin, Figure 6. Insulators with interfacial  $\sigma$ -FGM: a four-gradient tapered insulator (F-45-30-15-0) [31].<br>
3.1.4. Researches in Tsinghua University<br>
Following Z. An 's pioneering research regarding fluorination of epoxy resi



Electroluminescence as a parameter to characterize epoxy-based composites before and after fluorination<br>and age environmental and composites and after surface fluorination at -20kV [34].<br>Electroluminescence as a parameter Figure 7. Electroluminescence intensity of samples before and after surface fluorination at -20kV [34].<br>
Here electroluminescence intensity of samples before and after surface fluorination at -20kV [34].<br>
Electroluminesce Figure 7. Electroluminescence intensity of samples before and after surface fluorination at -20kV [34].<br>
Electroluminescence as a parameter to characterize epoxy-based composites before and after fluorination<br>
was introdu Figure 7. Electroluminescence intensity of samples before and after surface fluorination at -20kV [34].<br>Electroluminescence as a parameter to characterize epoxy-based composites before and after fluorination<br>was introduce Figure 7. Electroluminescence intensity of samples before and after surface fluorination at -20kV [34].<br>
Electroluminescence as a parameter to characterize epoxy-based composites before and after fluorination<br>
was introdu **Figure 7.** Electroluminescence intensity of samples before and after surface fluorination at -20kV [34]. Electroluminescence as a parameter to characterize epoxy-based composites before and after fluorination was introdu Electroluminescence as a parameter to characterize epoxy-based composites before and after fluorination<br>was introduced [34]. Here electroluminescence is defined as a surface light emission that may involve both<br>solid and was introduced [34]. Here electroluminescence is defined as a surface light emission that may involve both solid and gas emissions following impact by energetic carriers. It has to be distinguished from pure bulk emission

## AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 10 of 54

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 10 of 54<br>gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar cha AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 10 of 54<br>gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar cha AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 10 of 54<br>gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar cha AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 10 of 54<br>gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar cha AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 10 of 54<br>gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar cha gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar charges and can thereby increase the possibility of<br>undetermin gas-solid-conductor triple junction are suppressed. They emphasized that these micro-discharges are likely to<br>be a potential consequence of surface heteropolar charges and can thereby increase the possibility of<br>undetermin be a potential consequence of surface heteropolar charges and can thereby increase the possibility of undetermined surface flashover under both AC and DC voltage, which were also discussed in their follow-up research work undetermined surface flashover under both<br>research work [14, 79]. In 2017, the physic<br>on flashover voltage were explored and th<br>was preliminary studied( as shown in Fig<br>electro-corrosion performance by fluorina<br>confirmed t







Looking at the similarities of the results in these 4 different groups, we can conclude that several key<br>and 10th flashover [23].<br>
The similarities of the results in these 4 different groups, we can conclude that several k parameters play important roles in determining surface properties, among which the surface flashover roles in and 10th flashover [23].<br>
3.1.5. Analysis and discussion<br>
Looking at the similarities of the results in these 4 Figure 8. (a) Surface image of experimental samples before and surface flashover in SF<sub>6</sub> [35];(b) SEM<br>photographs of the discharge degraded surface of the virgin and the fluorinated samples respectively after the<br>5th and

| AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 |        |                               |                               |  |   |  |  |   |  |  |
|--|--------|-------------------------------|-------------------------------|--|---|--|--|---|--|--|
|  |        |                               |                               |  |   |  | Table 2. Fluorination test conditions and results of different research groups.<br><b>Fluorination parameter</b> |   |  |  |
| <b>Authors</b>                               | Ref.   | <b>Matrix</b>                 | Ambient<br>gas                | Surface conductivity test conditions<br>Temperature<br>(C) | Relative<br>humidity                          | <b>Fluorination</b><br>temperature<br>$(^{\circ}C)$                        | <b>Fluorination</b><br>time (mins)   | <b>Surface</b><br>conductivity<br>$(10^{-18}S)$   |  |  |
|  | $[21]$ | Epoxy<br>resin                | Air                           | 25   | 20%   | $\overline{\phantom{a}}$<br>$\overline{25}$<br>55<br>75<br>$\overline{95}$ | $\blacksquare$<br>30   | $7\phantom{.0}$<br>20<br>40<br>900<br>50000       |  |  |
| Z. An  | $[18]$ | Epoxy<br>resin                | High<br>purity $N_2$          | 25   | 20%   | $\overline{\phantom{a}}$<br>25<br>$\overline{55}$<br>$\overline{75}$<br>95 | $\blacksquare$<br>30   | 9<br>$\overline{10}$<br>30000<br>300000<br>800000 |  |  |
|  | $[22]$ | Epoxy<br>resin                | Air                           | 25   | 20%   | $\blacksquare$<br>50   | $\blacksquare$<br>10<br>30<br>60   | $\tau$<br>40000<br>10000<br>8000                  |  |  |
| G. Chen                                      | $[26]$ | Epoxy<br>resin                | Air                           | 25   | Before<br>drying<br>After<br>vacuum<br>drying | $\blacksquare$<br>50<br>$\blacksquare$<br>50                               | $\mathbb{L}$<br>60<br>$\blacksquare$<br>60   | 1886<br>4940<br>1406<br>2040                      |  |  |
|  |        |                               | $N_2$                         | 25   | After $N_2$<br>drying                         | $\overline{a}$<br>50   | $\sim$<br>60   | 1406<br>3480                                      |  |  |
|  | $[25]$ | Epoxy<br>resin                | Air                           | 25   | Not<br>mentioned                              | $\sim$<br>50   | $\blacksquare$<br>30<br>60   | 113.2<br>432<br>1006                              |  |  |
| B. Du  | $[31]$ | Epoxy<br>$/Al_2O_3$           | Air                           | 25   | Under 30%                                     | $\blacksquare$<br>25   | $\overline{\phantom{a}}$<br>15<br>$30\,$<br>45<br>60   | 450<br>800<br>1400<br>1790<br>1900                |  |  |
|  | $[24]$ | Epoxy<br>$/Al_2O_3$           | High<br>purity N <sub>2</sub> | 25   | Under $10\%$                                  | $\sim$<br>50   | $\blacksquare$<br>$\overline{15}$<br>30<br>$\overline{60}$   | 0.00097<br>370<br>$21\,$<br>0.86                  |  |  |
| J. He  | $[32]$ | Epoxy<br>$\overline{Al_2O_3}$ | Air                           | 16   | $10% - 14%$                                   | $\sim$<br>50   | $\blacksquare$<br>15<br>30<br>60   | 0.88<br>368<br>20.5<br>0.86                       |  |  |
|  | $[32]$ | Epoxy<br>$/Al_2O_3$           | $\mathrm{SF}_6$               | 16   | $10\%$ -14%                                   | $\blacksquare$<br>50   | 15<br>30<br>60   | 0.892<br>374<br>$21\,$<br>0.864                   |  |  |

surface conductivity values presented in different research studies. Two general conclusions can be obtained: 1. He  $\begin{array}{|c|c|c|c|c|}\n\hline 1, & 1.0\% & 10\% & 10\% & 14\% & 50 &$  $\frac{60}{6892}$ <br>  $\frac{6892}{60}$ <br>
However, based on the results of previously published literature, it is still difficult to confirm which parameter<br>
plays dominant role on surface charge decay process and surface flashover p 221 Abson the results of previously published literature, it is still difficult to confirm which parameter<br>plays dominant role on surface charge decay process and surface flashover property. Table 2 shows the<br>surface cond However, based on the results of previously published literature, it is still difficult to confirm which parameter<br>plays dominant role on surface charge decay process and surface flashover property. Table 2 shows the<br>surf plays dominant role on surface charge decay process and surface flashover property. Table 2 shows the surface conductivity values presented in different research studies. Two general conclusions can be obtained:<br>(1) The su

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 12 of 54<br>4 orders of magnitude in their values. Usually, the leakage current has very large difference with respect to<br>electric field, temperature and duration of applied d A orders of magnitude in their values. Usually, the leakage current has very large difference with respect to<br>electric field, temperature and duration of applied dc voltage. Meanwhile, if the measurement was repeated for<br>s A orders of magnitude in their values. Usually, the leakage current has very large difference with respect to electric field, temperature and duration of applied dc voltage. Meanwhile, if the measurement was repeated for s AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 12 of 54<br>4 orders of magnitude in their values. Usually, the leakage current has very large difference with respect to<br>electric field, temperature and duration of applied d AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 12 of 54<br>4 orders of magnitude in their values. Usually, the leakage current has very large difference with respect to<br>electric field, temperature and duration of applied d 4 orders of magnitude in their values. Usually, the leakage current has very large difference with respect to electric field, temperature and duration of applied dc voltage. Meanwhile, if the measurement was repeated for s 4 orders of magnitude in their values. Usually, the leakage current has very large difference with respect to<br>electric field, temperature and duration of applied dc voltage. Meanwhile, if the measurement was repeated for<br>s tric field, temperature and duration of applied dc voltage. Meanwhile, if the measurement was repeated for<br>ral times, the injected charges and depolarization process from previous tests can further influence the<br>age curren several times, the injected charges and depolarization process from previous tests can further influence the leakage current, resulting in a lower leakage current value. When it comes to samples after fluorination, we can

leakage current, resulting in a lower leakage current value. When it comes to samples after fluorination, we<br>can find some similarity that the surface conductivity can be increased by 3-5 orders of magnitude with short<br>fl can find some similarity that the surface conductivity can be increased by 3-5 orders of magnitude with short<br>fluorination time, while the long fluorination time results in a surface with conductivity similar to the<br>untre fluorination time, while the long fluorination time results in a surface with conductivity similar to the untreated samples. This finding is applicable to both alumina-doped epoxy and pure epoxy.<br>It has been widely accept untreated samples. This finding is applicable to both alumina-doped epoxy and pure epoxy.<br>
It has been widely accepted that a higher surface conductivity results in a higher surface charge decay rate.<br>
However, it should It has been widely accepted that a higher surface conductivity results in a higher surface charge decay rate.<br>
However, it should be pointed out that the increase in surface flashover voltage due to fluorination cannot<br>
m



Considering the feasibility of industrial applications, fluorination is applicable to insulators of any shape<br>size. However, it has disadvantages such as: the mechanism of the fluorination is complex, which needs<br>ther inv **Experiment since** in BF<sub>6</sub><br>
Flashbover voltage in BF<sub>6</sub><br>
Flashbover voltage in BF<sub>6</sub><br>
Experiment samples<br>
Experiment samples<br>
Experiment samples<br>
Experiment samples<br>
Experiment samples<br>
Experiment samples<br>
Experiment sam Figure 9. The DC surface flashover voltage of original and fluorinated samples for 15 min, 30 min and 60 min in air and SF<sub>6</sub>[32].<br>
Considering the feasibility of industrial applications, fluorination is applicable to ins **Experiment samples**<br>
Experiment samples<br>
Experiment samples for 15 min, 30 min and 60<br>
min in air and SF<sub>6</sub> [32].<br>
Considering the feasibility of industrial applications, fluorination is applicable to insulators of any s

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>the surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>after 5 days storage of the directly fluorinated samples in ambie AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>the surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>after 5 days storage of the directly fluorinated samples in ambie AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>the surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>after 5 days storage of the directly fluorinated samples in ambie AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>the surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>after 5 days storage of the directly fluorinated samples in ambie AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>r 5 days storage of the directly fluorinated samples in ambient air [

the surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>after 5 days storage of the directly fluorinated samples in ambient air [41]. However, the experiment was<br>cond the surface charge decay rate using sheet samples, and the results showed that there is no obvious aging effect<br>after 5 days storage of the directly fluorinated samples in ambient air [41]. However, the experiment was<br>cond after 5 days storage of the directly fluorinated samples in ambient air [41]. However, the experiment was conducted in the ambient air, which cannot demonstrate real operation condition subjected to temperature and electri conducted in the ambient air, which cannot demonstrate real operation condition s<br>electric field changes, so it cannot be regarded as a direct fluorination stability test<br>As reported in our recently published paper, the c



Bulk<br> **Plasma refers to an ionized gaseous medium which consists of a gas of ions and free electrons. Based on**<br> **Plasma refers to an ionized gaseous medium which consists of a gas of ions and free electrons. Based on**<br> **P** Figure 10. Stable surface leakage current and bulk leakage current changing trend with the increase of<br>temperature using a new short time fluorinated spacer [15].<br>3.2. Plasma treatment<br>Plasma refers to an ionized gaseous **Example 10.** Stable surface leakage current and bulk leakage current changing trend with the increase of temperature using a new short time fluorinated spacer [15].<br> **3.2. Plasma treatment**<br>
Plasma **refers** to an ionized Figure 10. Stable surface leakage current and bulk leakage current changing trend with the increase of temperature using a new short time fluorinated spacer [15].<br>
3.2. Plasma treatment<br>
Plasma refers to an ionized gaseous 3.2. Plasma treatment<br>
Plasma refers to an ionized gaseous medium which consists of a gas of ions and free electrons. Based on<br>
its unique property, it can be used to modify dielectric surface, modifying surface trap level enhancement.

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>3.2.1. Researches in Chinese Academy of Sciences<br>Electrons in non-thermal plasmas can induce molecule excitation, ioniza AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 14 of 54<br>
1. Researches in Chinese Academy of Sciences<br>
Electrons in non-thermal plasmas can induce molecule excitation, ionization and dissociation, hence,<br>
1. Iting in th AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 14 of 54<br>3.2.1. Researches in Chinese Academy of Sciences<br>Electrons in non-thermal plasmas can induce molecule excitation, ionization and dissociation, hence,<br>resulting in AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 14 of 54<br>3.2.1. Researches in Chinese Academy of Sciences<br>Electrons in non-thermal plasmas can induce molecule excitation, ionization and dissociation, hence,<br>resulting in AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 14 of 54<br>3.2.1. Researches in Chinese Academy of Sciences<br>Electrons in non-thermal plasmas can induce molecule excitation, ionization and dissociation, hence,<br>resulting in 3.2.1. Researches in Chinese Academy of Sciences<br>Electrons in non-thermal plasmas can induce molecule excitation, ionization and dissociation, hence,<br>resulting in the chemical bonds breaking for surface modification [80, 8 surface potential decay of samples after the plasma treatment. Samples were charged by corona disconsistion, senection, i.e., researchly in the chemical bonds breaking for surface modification [80, 81]. T. Shao *et al.* pe Electrons in non-thermal plasmas can<br>resulting in the chemical bonds breaking<br>pioneering studies over DBD plasma treatm<br>effectively increases the surface hydrophili<br>rate [38]. Meanwhile, the anti-aging proper<br>surface pote



AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>amplitude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>the surface potential decay was slower on the samples measured after AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>amplitude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>the surface potential decay was slower on the samples measured after AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>amplitude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>the surface potential decay was slower on the samples measured after 4

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>itude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>urface potential decay was slower on the samples measured after 4 days, w **AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1**<br>
amplitude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>
the surface potential decay was slower on the samples measured af amplitude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>the surface potential decay was slower on the samples measured after 4 days, while the aging resistance of the<br>atmo amplitude of -4.5 kV, the temperature was 20 °C and the relative humidity was 20%. The results showed that<br>the surface potential decay was slower on the samples measured after 4 days, while the aging resistance of the<br>atm the surface potential decay was slower on the samples measured after 4 days, while the aging resistance of the<br>atmospheric-pressure dielectric barrier discharge (AP-DBD) etching method is not improved significantly.<br>Based atmospheric-pressure dielectric barrier discharge (AP-DBD) etching method is not improved significantly.<br>Based on their previous research results, they further conducted in-depth research on sample modification<br>methods bas Based on their previous research results, they further conducted in-depth research on sample modification<br>methods based on plasma treatment in 2017 [39, 40, 43]. They found out that the plasma deposition process<br>can increa methods based on plasma treatment in 2017 [39, 40, 43]. They found out that the plasma deposition process<br>can increase the aging resistance more effective than the direct plasma treatment mentioned in their previous<br>work [ can increase the aging resistance more effective than the direct plasma treatment mentioned in their previous<br>work [38]. In their test setup, non-thermal plasma generated by gliding arc discharge driven by high-frequency<br> work [38]. In their test setup, non-thermal plasma got<br>high-voltage power supply are used to deposit Si<br>precursor is tetraethyl orthosilicate (TEOS) [43]. T<br>thin film with a thickness of 219nm containing Si-C<br>surface. Mea voltage power supply are used to deposit SiO<sub>2</sub> film on the surface of epoxy resin, and the reaction<br>ursor is tetraethyl orthosilicate (TEOS) [43]. They realized that when the deposition time exceeded 5s, a<br>film with a thi precursor is tetracthyl orthosilicate (TEOS) [43]. They realized that when the deposition time exceeded 5s, a<br>thin film with a thickness of 219nm containing Si-O-Si and Si-OH groups can be stably formed on the epoxy<br>surfac

thin film with a thickness of 219nm containing Si-O-Si and Si-OH groups can be stably formed on the epoxy<br>surface. Meanwhile, with this surface layer, the water contact angle and the surface resistivity were<br>significantly surface. Meanwhile, with this surface layer, the water contact angle and the surface resistivity were significantly reduced compared with pure epoxy samples, which increases surface charge decay rate significantly [40].<br>T significantly reduced compared with pure epoxy samples, which increases surface charge decay rate significantly [40].<br>
T. Shao *et al.* further studied the feasibility of plasma deposition on surface charge property and d significantly [40].<br>
T. Shao *et al.* further studied the feasibility of plasma deposition on surface charge property and<br>
deposited SiO<sub>s</sub> thin film on the surface of epoxy resin by AP-DBD [37, 39]. The results showed th T. Shao *et al.* further studied the feasibility of plasma deposition on surface charge property and deposited SiO<sub>s</sub> thin film on the surface of epoxy resin by AP-DBD [37, 39]. The results showed that the initial surface deposited SiO<sub>x</sub> thin film on the surface of epoxy resin by AP-DBD [37, 39]. The results showed that the initial surface charge density was reduced by 12% and the flashover voltage was increased by 42% after plasma deposi surface charge density was reduced by 12% and the flashover voltage was increased by 42% after plasma<br>deposition treatment. They believed that the mechanism for the increasing of these properties is due to the fact<br>that deposition treatment. They believed that the mechanism for the increasing of these properties is due to the fact<br>that SiO<sub>s</sub> films with a thickness of 50-200 nm introduce shallow traps, which increases the surface<br>conducti that  $3O_x$  mins with a threatiess of  $30-200$  min intothce shantow the conductivity and thereby reduce the accumulation of surface charges. In 20 three methods of plasma etching, plasma deposition and direct fluorination methods of plasma etching, plasma deposition and direct fluorination on the basis of previous researches<br>42]. The surface charge decay rate of epoxy based samples after DBD deposition (96%) and fluorination<br>9) is higher th [41, 42]. The surface charge decay rate of epoxy based samples after DBD deposition (96%) and fluorination (95%) is higher than DBD etching (34%) [42]. The results from the above mentioned studies indicate that AP-DBD dep

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 16 of 54<br>
conductivity reaches  $1.4 \times 10^{-17}$ S which is 2 orders of magnitude higher than that of untreated samples.<br>
Meanwhile, the correlation between surface flashover a AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 16 of 54<br>
conductivity reaches  $1.4 \times 10^{17}$ S which is 2 orders of magnitude higher than that of untreated samples.<br>
Meanwhile, the correlation between surface flashover AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 16 of 54<br>conductivity reaches  $1.4 \times 10^{-17}$ S which is 2 orders of magnitude higher than that of untreated samples.<br>Meanwhile, the correlation between surface flashover an AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
conductivity reaches  $1.4 \times 10^{-17}$ S which is 2 orders of magnitude higher than that c<br>
Meanwhile, the correlation between surface flashover and the surface conductivity<br>
surf



Table 3 shows the key parameters selected for each research group according to different treatment<br>ods. Most of the results show an upward trend regarding the surface conductivity [44].<br>
Table 3 shows the key parameters s **Example 12.** Relation between surface flashover voltage and surface conductivity [44].<br> **Eigure 12.** Relation between surface flashover voltage and surface conductivity [44].<br>
3.2.3. Analysis and discussion<br>
Table 3 show Surface Conductivity (S)<br> **Sample 12.** Relation between surface flashover voltage and surface conductivity [44] .<br>
3.2.3. Analysis and discussion<br>
Table 3 shows the key parameters selected for each research group according Figure 12. Relation between surface flashover voltage and surface conductivity [44] .<br>
3.2.3. Analysis and discussion<br>
Table 3 shows the key parameters selected for each research group according to different treatment<br>
met 3.2.3. Analysis and discussion<br>Table 3 shows the key parameters selected for each research group according to different treatment<br>methods. Most of the results show an upward trend regarding the surface conductivity of samp S.2.3. Analysis and distussion<br>Table 3 shows the key parameters selected for each research group according to different treatment<br>methods. Most of the results show an upward trend regarding the surface conductivity of samp Table 3 shows the key parameters selected for each research group according to different treatment<br>methods. Most of the results show an upward trend regarding the surface conductivity of samples after plasma<br>treatment, wit methods. Most of the results show an upward trend regarding the surface conductivity of samples after plasma<br>treatment, with the increasing value of 1 to 4 orders of magnitude. However, it is worth noting that contrary to<br> studied.

| Research | Ref.   | Table 3. Treatment time and results of different plasma processing methods.<br><b>Treatment type</b> | <b>Processing time</b>      | <b>Surface</b>             |
|----------|--------|--|-----------------------------|----------------------------|
| group    |        |  |                             | conductivity $(10^{-18}s)$ |
|          | $[43]$ | Untreated  | $\boldsymbol{0}$            | 1810                       |
|          |        | Plasma enhanced chemical   | 1s<br>$\overline{3s}$       | 3810<br>6390               |
|          |        | vapor deposition (PECVD) to  | $\overline{5s}$             | 24100                      |
|          |        | deposit SiO <sub>2</sub> thin films  | 10s                         | 85100                      |
|          |        |  | 15s                         | 113000                     |
|          |        | Untreated  | $\mathbf{0}$                | 30000                      |
|          |        | AP-DBD etching   | 10s                         | 68000                      |
|          | $[38]$ |  | 60s                         | 190000                     |
|          |        |  | 180s                        | 250000                     |
|          | $[37]$ | Untreated  | $\mathbf{0}$                | 900                        |
|          |        | APPJ Plasma Treatment to<br>Deposit SiOx Film  | 1 <sub>min</sub>            | 9000                       |
|          |        |  | 3mins                       | 70000                      |
|          |        |  | 5mins                       | 60000                      |
| T. Shao  |        | Untreated  | 10mins<br>0 <sub>mins</sub> | 30000<br>900               |
|          | $[42]$ | AP-DBD etching   | 5mins                       | 7000                       |
|          |        | AP-DBD Plasma Treatment to   |                             |                            |
|          |        | Deposit Ar/TEOS  | 10mins                      | 300000                     |
|          |        | Direct fluorination  | 30mins (At 50 °C)           | 90000                      |
|          |        | Untreated  | $\boldsymbol{0}$            | 270.3                      |
|          |        | AP-DBD Plasma Treatment to   | <b>5mins</b>                | 1000000                    |
|          | $[41]$ | Deposit Ar/TEOS  | 10mins                      | 1010000                    |
|          |        |  | 15mins(At 50 °C)            | 3330                       |
|          |        | Direct fluorination  | $30 \text{mins} (At 50 °C)$ | 50000                      |
|          |        |  | 60mins(At 50 $°C$ )         | $1\,00000$                 |
|          |        | Untreated  | $\overline{0}$              | 2230                       |
|          | $[39]$ |  | 3min                        | 2000000<br>5000000         |
|          |        | AP-DBD deposited SiOx film   | 5mins<br>10mins             | 54700000                   |
|          |        | Untreated  | $\boldsymbol{0}$            | 0.1                        |
|          |        |  | 1 <sub>min</sub>            | 13                         |
| D. Min   | $[44]$ | HD-1B plasma modification  | 3min                        | 14.5                       |
|          |        | device   | 5min                        | 10                         |

3.3. Coatings<br>
Commonly used coatings to modify surface charge<br>
spray coatings, dipping and plasma coatings.<br>
3.3.1. Research review<br>
Nano-TiO<sub>2</sub>/EP coatings can increase surface charge

Commonly used coatings to modify surface charge behaviors include: magnetron sputtering coatings,<br>y coatings, dipping and plasma coatings.<br>1. Research review<br>Nano-TiO<sub>2</sub>/EP coatings can increase surface charge decay of epo *et al.* [46]. When the content of nano-TiO<sub>2</sub> particles is 1% and 3%, the surface charge is mainly concentrated Nano-TiO<sub>2</sub>/EP coatings can increase surface charge decay of epoxy resin, which was developed by Y. Tu *et al* Commonly used coatings to modify surface charge behaviors include: magnetron sputtering coatings, spray coatings, dipping and plasma coatings.<br>
3.3.1. Research review<br>
Nano-TiO<sub>2</sub>/EP coatings can increase surface charge de

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 18 of 54<br>
charge settles near the grounded electrode. When the particle content is 3%, the surface conductivity reaches a<br>
maximum value which is  $2 \times 10^{-17}$ S [45]. AUTHOR SUBMITTED MANUSCRIPT - NANO-1272<br>charge settles near the grounded electrode. When the particle content is 3%<br>maximum value which is  $2 \times 10^{-17}$ S [45].



by dipping and found out that the flashover characteristics of the samples are increased dramatically, as shown **EVALUATE 13** [82]. However, they verified that when the content of nanographene reaches 0.15%, the flashover voltage of the uncoated and epoxy (EP)/graphene (GR) coated insulators [82].<br>
Meanwhile, B.Du *et al.* prepared **Figure 13.** Weibull distributions of flashover voltages of the uncoated and epoxy (EP)/graphene (GR) coated insulators [82].<br> **Figure 13.** Weibull distributions of flashover voltages of the uncoated and epoxy (EP)/graphe Flashover voltage (kV)<br>Insulators [82].<br>
Meanwhile, B.Du *et al.* prepared epoxy (EP)/graphene (GR) coated insulators with different doping ratios<br>
by dipping and found out that the flashover characteristics of the samples insulators [82].<br>
Meanwhile, B.Du *et al.* prepared epoxy (EP)/graphene (GR) coated insulators with different doping raby dipping and found out that the flashover characteristics of the samples are increased dramatically, Meanwhile, B.Du *et al.* prepared epoxy (EP)/graphene (GR) coated insulators with different doping ratios<br>lipping and found out that the flashover characteristics of the samples are increased dramatically, as shown<br>igure Meanwhile, B.Du *et al.* prepared epoxy (EP)/graphene (GR) coated insulators with different doping ratios<br>by dipping and found out that the flashover characteristics of the samples are increased dramatically, as shown<br>in in Figure 13 [82]. However, they verified that when the content of nanographene reaches 0.15%<br>voltage of EP / GR coated insulators is lower than that of uncoated insulators. They believed<br>proper nanographene content on th



AUTHOR SUBMITTED MANUSC<br>3.3.2. Analysis and discussion<br>Table 4 summarized the feature parameters regarding<br>groups. In addition to the parameters researches focusing of AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>2. Analysis and discussion<br>Table 4 summarized the feature parameters regarding epoxy coatings in the above mentioned research<br>typs. In addition to the parameters researches focu AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>3.3.2. Analysis and discussion<br>Table 4 summarized the feature parameters regarding epoxy coatings in the above mentioned research<br>groups. In addition to the parameters researche AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>3.3.2. Analysis and discussion<br>Table 4 summarized the feature parameters regarding epoxy coatings in the above mentioned research<br>groups. In addition to the parameters research **by introducing the charge carrier mobility** introduced by nano-SiO<sub>2</sub> particle contings in the above mentioned research groups. In addition to the parameters researches focusing on after fluorination or plasma treatment, 3.3.2. Analysis and discussion<br>
Table 4 summarized the feature parameters regarding epoxy coatings in the above mentioned rese<br>
groups. In addition to the parameters researches focusing on after fluorination or plasma tre in the above mentioned research<br>on or plasma treatment, i.e. surface<br>xplain charge tailoring mechanism<br>carrier mobilities of the coatings,<br> $/(V \cdot s)$  and  $17.5 \times 10^{-13}$  m<sup>2</sup> / (V·s),<br>ngs with a doping amount of 3wt%<br>been v esearch<br>surface<br>hanism<br>patings,<br>/ (V·s),<br>f 3wt%<br>inhibit 3.3.2. Analysis and discussion<br>Table 4 summarized the feature parameters regarding epoxy coatings in the above mentioned research<br>groups. In addition to the parameters researches focusing on after fluorination or plasma t Table 4 summarized the feature parameters regarding epoxy<br>groups. In addition to the parameters researches focusing on after<br>conductivity and surface roughness, these two research groups att<br>by introducing the charge carr e parameters regarding epoxy coatings in the above mentioned research<br>s researches focusing on after fluorination or plasma treatment, i.e. surface<br>these two research groups attempt to explain charge tailoring mechanism<br>o groups. In addition to the parameters researches focusing on after fluorination or plasma treatment, i.e. surface<br>conductivity and surface roughness, these two research groups attempt to explain charge tailoring mechanism conductivity and surface roughness, these two research groups attempt to explain charge tailoring mechanism<br>by introducing the charge carrier mobility. Y. Tu *et al* observed that, the carrier mobilities of the coatings,<br> by introducing the charge carrier mobility. Y. Tu *et al* observed that, the carrier mobilities of the coatings, with 1 wt% and 3 wt% micro-SiO<sub>2</sub> particles, reach as high as  $11 \times 10^{-13}$  m<sup>2</sup> / (V·s) and  $17.5 \times 10^{-13}$ er mobilities of the coatings,<br>
(i) and  $17.5 \times 10^{-13}$  m<sup>2</sup> / (V·s),<br>
ith a doping amount of 3wt%<br>
verified effectively to inhibit<br>
onducted by B. Du *et al*, the<br>
ge of up to 33kV, while the<br>
(V·s) compared with other<br> with 1 wt% and 3 wt% micro-SiO<sub>2</sub> particles, reach as high as  $11 \times 10^{-13}$  m<sup>2</sup> / (V·s) and  $17.5 \times 10^{-13}$  m<sup>2</sup> / (V·s),<br>while the carrier mobility introduced by nano-SiO<sub>2</sub> particle composite coatings with a doping amo while the carrier mobility introduced by nano-SiO<sub>2</sub> particle composite coatings with a doping amount of 3wt%<br>is the highest around 86 × 10<sup>-13</sup> m<sup>2</sup> / (V·s). The above three samples have been verified effectively to inhi is the highest around  $86 \times 10^{-13}$  m<sup>2</sup> / (V·s). The above three samples have been verified effectively to inhibit<br>the accumulation of surface charges on epoxy resins. However, in the study conducted by B. Du *et al*, th the accumulation of surface charges on epoxy resins. However, in the study conducted by B. Du *et al*, the 0.1wt% nanographene / EP composite coating results in a DC flashover voltage of up to 33kV, while the carrier mobi 0.1wt% nanographene / EP composite coating results in a DC flashover voltage of up to 33kV, while the carrier mobility of this sample shows the lowest value around  $0.14 \times 10^{13}$  m<sup>2</sup> / (V·s) compared with other samples. carrier mobility of this sample shows the lowest value around  $0.14 \times 10^{-13}$  m<sup>2</sup> / (V·s) compared with other samples. However, the carrier mobility of the samples in [45] is 2 orders of magnitude higher than that in [82 samples. However, the carrier mobility of the samples in [45] is 2 orders of magnitude higher 1<br>Therefore, it can be assumed that the carrier mobility can only be used as an auxiliary basisurface flashover voltage, while o it can be assumed that the carrier mobility can only be used as an auxiliary basis for explaining<br>shover voltage, while other factors such as the coating material intrinsic property, surface<br>ies, etc. need to be comprehens arge controlling methods on insulators need to<br>
e coating and its stability against the cold and he<br>
mits the industrialization of such coatings method<br> **Die 4.** Relationship between Carriers and Doping<br>
No./ref<br>
Coating m France and to be further explored.<br>
cold and heat cycles still need :<br>
ings methods.<br>
and Doping Amount of Differer<br>
The average Coating Coating doped thickness<br>
coating doped 10<sup>-6</sup>m ators need to be further explored. In action<br>the cold and heat cycles still need further<br>patings methods.<br>Figures of the particle size of the coating doped<br>netricles interfering the coating doped<br>particles  $10^5$ m<br>netricle ored. In addition, the anti-aging<br>
eed further consideration, which<br>
ferent Coating Materials.<br>
Coating doping<br>
content<br>
wt%<br>  $\frac{10^{-13}m^2/(V \cdot s)}{10^{-13}m^2/(V \cdot s)}$ 

| Research<br>group | No./ref | <b>Coating material</b>              | The average<br>particle size of the<br>coating doped<br>particles 10 <sup>-9</sup> m | Coating<br>thickness<br>$10-6m$ | <b>Coating doping</b><br>content<br>wt% | Carrier<br>mobility<br>$10^{-13}m^2/(V \cdot s)$ |
|-------------------|---------|--------------------------------------|--|---------------------------------|---|--|
|                   |         | Nano-SiO <sub>2</sub> / EP composite |  |                                 | $\boldsymbol{0}$                        | 5.2  |
|                   | $[45]$  | coating                              | 60   |                                 | 3                                       | 86   |
| Y. Tu             |         |                                      |  | $170 - 190$                     | 5                                       | 30   |
|                   |         | Micron $SiO2$ / EP composite         |  |                                 |   | 11   |
|                   | $[45]$  | coating                              | 700  |                                 | 3                                       | 17.5   |
|                   |         |                                      |  |                                 | 5                                       | 9.5  |
|                   |         |                                      |  |                                 | $\Omega$                                | 0.38   |
| B. Du             | $[82]$  | Nanographene / EP composite          | 500-5000   | Not                             | 0.05                                    | 0.18   |
|                   |         | coating                              |  | mentioned                       | 0.1                                     | 0.14   |
|                   |         |                                      |  |                                 | 0.15                                    | 0.46   |

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 20 of 54<br>In addition to the methods already mentioned, the following techniques are also discussed by researchers<br>andidates to modify surface charge behaviors, which includ AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 20 of 54<br>In addition to the methods already mentioned, the following techniques are also discussed by researchers<br>as candidates to modify surface charge behaviors, which in AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.<br>In addition to the methods already mentioned, the following techniques a<br>as candidates to modify surface charge behaviors, which includes: gamma ray<br>ozone treatment, and radical s AUTHOR SUBMITTED MAI<br>
In addition to the methods already mentioned, th<br>
as candidates to modify surface charge behaviors, wh<br>
ozone treatment, and radical scavenger treatment.<br>
3.4.1. Gamma rays<br>
In 2010, Y. Gao *et al.* f In addition to the methods already mentioned, the following techniques are also discussed by researchers<br>andidates to modify surface charge behaviors, which includes: gamma ray treatment, roughness treatment,<br>ne treatment,

In addition to the methods already mentioned, the following techniques are also discussed by researchers<br>as candidates to modify surface charge behaviors, which includes: gamma ray treatment, roughness treatment,<br>ozone tre as candidates to modify surface charge behaviors, which includes: gamma ray treatment, roughness treatment, ozone treatment, and radical scavenger treatment.<br>
3.4.1. Gamma rays<br>
In 2010, Y. Gao *et al.* found that the surf ozone treatment, and radical scavenger treatm<br>
3.4.1. Gamma rays<br>
In 2010, Y. Gao *et al*. found that the st<br>
epoxy sample being treated by gamma rays,<br>
using the 1000 kGy irradiated sample [47, 48]<br>
in trap depth.<br>
3.4.2. 3.4.1. Gamma rays<br>In 2010, Y. Gao *et al.* found that the surface charge deca<br>epoxy sample being treated by gamma rays, and the surface po<br>using the 1000 kGy irradiated sample [47, 48]. They attributed t<br>in trap depth.<br>3. In 2010, Y. Gao *et al.* found that the surface charge decay rate of epoxy insulator is accelerated after all the surface by gamma rays, and the surface potential decay rate shows the best results when the 1000 kGy irradia epoxy sample being treated by gamma rays, and the surface potential decay rate shows the best results when<br>using the 1000 kGy irradiated sample [47, 48]. They attributed the increased charge dissipation to the decrease<br>in

using the 1000 kGy irradiated sample [47, 48]. They attributed the increased charge dissipation to the decrease<br>in trap depth.<br>3.4.2. Surface roughness treatment<br>In 1983, Nakaishi K *et al.* found that unpolished cylindric





AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>accumulate at the junction of the polished and unpolished areas, as shown in Figure 16. Based on such<br>findings, they believed that the uneven conduction on the insulator surface AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>accumulate at the junction of the polished and unpolished areas, as shown in Figure 16. Based on such<br>findings, they believed that the uneven conduction on the insulator surface AUTHOR SUBMITTED MA<br>
accumulate at the junction of the polished and un<br>
findings, they believed that the uneven conduction of<br>
accumulation [84].



Figure 16. (a) Sand blasted region on the spacer. (b) Charge distribution after 240 hours' voltage application<br>of the spacer with nonuniform surface conductivity [84].<br>Further, J. Xue *et al.* studied the surface charging **Examples 19**<br>
The surface flashover 16. (a) Sand blasted region on the spacer. (b) Charge distribution after 240 hours' voltage application<br>
for the spacer with nonuniform surface conductivity [84].<br>
Further, J. Xue *et* **Figure 16.** (a) Sand blasted region on the spacer. (b) Charge distribution after 240 hours' voltage application<br>for the spacer with nonuniform surface conductivity [84].<br>Further, J. Xue *et al.* studied the surface charg (a)<br>
(b)<br> **Eigure 16.** (a) Sand blasted region on the spacer. (b) Charge distribution after 240 hours' voltage application<br>
for the spacer with nonuniform surface conductivity [84].<br>
Further, J. Xue *et al.* studied the s **Figure 16.** (a) saline basised region on the spacet. (b) Change distinuation antet 240 nours voltage application<br>for the spacer with nonuniform surface conductivity [84].<br>Further, J. Xue *et al.* studied the surface cha Further, J. Xue *et al.* studied the surface charging property and surface flashover characteristics in SF<sub>6</sub> / N<sub>2</sub> mixed systems using epoxy alumina insulator samples with different surface roughness [85]. Under positiv mixed systems using epoxy alumina insulator samples with different surface roughness [85]. Under positive<br>DC voltage, the average surface flashover voltages for samples with surface roughness of 0.58 µm, 5.19 µm,<br>7.48 µm, DC voltage, the average surface flashover voltages for samples with surface roughness of 0.58  $\mu$ m, 5.19  $\mu$ m, 7.48  $\mu$ m, and 9.24  $\mu$ m were 15.48 kV, 16.24 kV, 16.76 kV, and 17.55 kV, respectively. Compared with the u 7.48 µm, and 9.24 µm were 15.48 kV, 16.24 kV, 16.76 kV, and 17.55 kV, respectively. Compared with the untreated surface (0.58 µm), the positive DC voltage increased by 4.86% (5.19 µm), 8.27% (7.48 µm), and 13.32% (9.24 µm) untreated surface (0.58 µm), the positive DC voltage increased by 4.86% (5.19 µm), 8.27% (7.48 µm), and<br>13.32% (9.24 µm), respectively (as shown in Figure 17). The DC flashover voltage can be increased by 20%<br>to 25% after 13.32% (9.24 µm), respectively (as shown in Figure 17). The DC flashover voltage can be increased by 20% to 25% after the surface is roughened. They believed that the increase in surface flashover voltage firstly is mainly



The effect of ozone treatment on the surface flashover performance of epoxy / Al<sub>2</sub>O<sub>3</sub> composite was<br>magnitude compares [85].<br>The effect of ozone treatment on the surface flashover performance of epoxy / Al<sub>2</sub>O<sub>3</sub> compos Stage II<br>
Figure 17. Surface flashover performance on spacer with different amount of surface roughness under<br>
positive DC voltage stress [85].<br>
3.4.3. Ozone treatment<br>
The effect of ozone treatment on the surface flashov **Figure 17.** Surface flashover performance on spacer with different amount of surface roughness under positive DC voltage stress [85].<br>
3.4.3. Ozone treatment<br>
The effect of ozone treatment on the surface flashover perfor **Figure 17.** Surface flashover performance on spacer with different amount of surface roughness under positive DC voltage stress [85].<br>
3.4.3. Ozone treatment<br>
The effect of ozone treatment on the surface flashover perfor 3.4.3. Ozone treatment<br>The effect of ozone treatment on the surface flashover performance of epoxy / Al<sub>2</sub>O<sub>3</sub> composite was<br>studied and the results showed that the surface conductivity by ozone treatment for 4h is increa The effect of ozone treatment on the surface flashover performance of epoxy / Al<sub>2</sub>O<sub>3</sub> composite was studied and the results showed that the surface conductivity by ozone treatment for 4h is increased by 2 orders of magn



[49].

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>In 2013, H. Tarik Baytekin *et al.* proposed that scavenging for free radicals from surface could be a more<br>ficient way to increase surface charge decay rate, than controlling t AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>In 2013, H. Tarik Baytekin *et al.* proposed that scavenging for free radicals from surface could be a more<br>efficient way to increase surface charge decay rate, than controlling argued that these free radicals coexist with the charge and stabilize them on the surface could be a more defficient way to increase surface charge decay rate, than controlling the surface charges itself [50]. They argued 54 AUTHOR SUBMITTED MANUSCRIPT - NAI<br>
In 2013, H. Tarik Baytekin *et al.* proposed that scavenging for<br>
efficient way to increase surface charge decay rate, than control<br>
argued that these free radicals coexist with the c



They performed a series of charging experiments with native polymers, as well as polymers doped with and anounts of chemical substances scavenging the radicals with a series of charging experiments with native polymers, a Figure 19. (a) Four kinds of radical substances scavenging the radicals such as (as shown in Figure 19. (a) Four kinds of radical such as (as shown in Figure 19. (a) Four kinds of radical such as (as shown in Figure 19. ( Figure 19. (a) Four kinds of radical scavengers; (b) charge decay of pure PDMS charged by corona discharge either (+) or (-), and free radicals(white spots) distribution of different samples in 30 minutes;(c) charge decay **Figure 19.** (a) Four kinds of radical scavengers; (b) charge decay of pure PDMS charged by corona discharge either (+) or (-), and free radicals(white spots) distribution of different samples in 30 minutes;(c) charge dec Figure 19. (a) Four knuss of aduced scavengers, (b) clarge decay of pure FDMS clarge diversion of different samples in 30 minutes;(c) charge decay of PDMS/5 mM DPPH charged by corona discharge either (+) or (-), and free effectively during contact charging. Figure 19 (b) and (c) show that under the corona discharge, the surface charge enter ( $\pm$ ) or  $(-)$ , and the radicals (white spots) distribution of different samples in 30 minutes [50] They performed a series of charging experiments with native polymers, as well as polymers doped with<br>small amounts of chemical substances scavenging the radicals such as (as shown in Figure 19<br>(a))(T)-a-tocopherol (vitamin all amounts of chemical substances scavenging the radicals such as (as shown in Figure 19<br>
()(T)-a-tocopherol (vitamin E), bis(1-octyloxy-2,2,6,6-tetramethyl-4-piperidyl) sebacate (HALS),<br>
2-diphenyl-1-picrylhydrazyl (DPPH (a))(T)-a-tocopherol (vitamin E), bis(1-octyloxy-2,2,6,6-tetramethyl-4-piperidyl) sebacate (HALS),<br>2,2-diphenyl-1-picrylhydrazyl (DPPH) or 2,2-diphenyl-1-picryl hydrazine (DPPH-H), and the results showed<br>that the presence 2,2-diphenyl-1-picrylhydrazyl (DPPH) or 2,2-diphenyl-1-picryl hydrazine (DPPH-H), and the results showed<br>that the presence of free radical scavengers reduced the tendency of the polymer to generate static electricity<br>effec

that the presence of free radical scavengers reduced the tendency of the polymer to generate static electricity<br>effectively during contact charging. Figure 19 (b) and (c) show that under the corona discharge, the surface<br>c

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 24 of 54<br>and in SF<sub>6</sub>, we found that the surface potential decay rate becomes invalid with the same charge decay rate as<br>that of the untreated samples (as shown in Figure AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>and in SF<sub>6</sub>, we found that the surface potential decay rate becomes invalid with the sam<br>that of the untreated samples (as shown in Figure 20).<br> $\begin{bmatrix} -2000 \\ -2000 \end{bmatrix}$ 



Figure 20. Epoxy surface potential decay curve of epoxy resin treated with astaxanthin and stored at 0.1<br>
Times after treatment<br>  $\frac{200}{200}$  Times after treatment<br>  $\frac{200}{200}$  Times after treatment<br>  $\frac{200}{200}$  Time **Figure 20.** Epoxy surface potential decay curve of epoxy resin treated with astaxanthin and stored at 0.1 MPa SF<sub>6</sub> for different certain times (Soak for 10 minutes, test after drying).<br>The charging mechanism of contact Figure 20. Epoxy surface potential decay curve of epoxy resin treated with astaxanthin and stored at 0.1<br>MPa SF<sub>6</sub> for different certain times (Soak for 10 minutes, test after drying).<br>The charging mechanism of contact el Figure 20. Epoxy surface potential decay curve of epoxy resin treated with astaxanthin and stored at 0.1 MPa SF<sub>6</sub> for different certain times (Soak for 10 minutes, test after drying).<br>The charging mechanism of contact ele Figure *U*. Epoxy surface polential receives the surface of the surface with a surface of MPa SF<sub>6</sub> for different certain times (Soak for 10 minutes, test after drying).<br>The charging mechanism of contact electrification-(t The charging mechanism of contact electrification-(triboelectrification) and electrification due to electric<br>fields or corona are very different from each other. One involves material transfer, surface oxidation,<br>reorienta fields or corona are very different from each<br>reorientation of polar molecules; however the oth<br>impact of specific physical or chemical reaction p<br>H. Tarik Baytekin 's study, they used PDMS, an<br>very active at the surface ( reorientation of polar indecutes, nowever the other involvement<br>impact of specific physical or chemical reaction processes<br>H. Tarik Baytekin 's study, they used PDMS, an elastom<br>very active at the surface (and also in the Tarik Baytekin 's study, they used PDMS, an elastomer with very low Tg, and molecules or chains were<br>ry active at the surface (and also in the volume) at the room temperature. For this reason, antioxidant<br>blecules could fi

very active at the surface (and also in the volume) at the room temperature. For this reason, antioxidant<br>molecules could find the active groups easily at the surface, and discharg occured rapidly. Epoxy may not<br>have these molecules could find the active groups easily at the surface, and discharg occured rapidly. Epoxy may not<br>have these characteristics.<br>3.4.5. Analysis and discussion<br>Table 5 shows the results obtained from different treatme and the samples of the sample for 2 h. Meanwhile, the increase surface in this section. It can be found from<br>
185] and [49] that compared with the roughness treatment that can increase surface conductivity by 1 order of<br>
1 3.4.5. Analysis and discussion<br>Table 5 shows the results obtained from different treatment methods in this section. It can be found from<br>[85] and [49] that compared with the roughness treatment that can increase surface co 3.4.5. Analysis and discussion<br>
Table 5 shows the results obtained from different treatment methods in this section. It can be found from<br>
[85] and [49] that compared with the roughness treatment that can increase surface

60

BE NOT AN AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
be noted that due to the differences in samples and experimental setup, it would be difficult to make<br>
comparisons regarding surface flashover properties.<br>
The radica AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R<br>be noted that due to the differences in samples and experimental setup, if<br>comparisons regarding surface flashover properties.<br>The radical scavenger treatment method uses the coe

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
noted that due to the differences in samples and experimental setup, it would be difficult to make<br>
mparisons regarding surface flashover properties.<br>
The radical scavenger tre AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>be noted that due to the differences in samples and experimental setup, it would be difficult to make<br>comparisons regarding surface flashover properties.<br>The radical scavenger t AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>be noted that due to the differences in samples and experimental setup, it would be difficult to make<br>comparisons regarding surface flashover properties.<br>The radical scavenger t be noted that due to the differences in samples and experimental setup, it would be difficult to make<br>comparisons regarding surface flashover properties.<br>The radical scavenger treatment method uses the coexistence of these be noted that due to the differences in samples and experimental setup, it would be difficult to make<br>comparisons regarding surface flashover properties.<br>The radical scavenger treatment method uses the coexistence of these comparisons regarding surface flashover properties.<br>The radical scavenger treatment method uses the coexistence of these free radicals to achieve the purpose of<br>eliminating charges indirectly by eliminating free radicals. The radical scavenger treatment method uses the coexistence of these free radicals to achieve the purpose of eliminating charges indirectly by eliminating free radicals. However, for the radical elimination mechanism of ep eliminating charges indirectly by eliminating free radicals. Howe<br>epoxy based samples, more studies should be carried out. Me<br>property should be more important while dealing with products<br>very good property in surface char The first method is the dealing with products in industrial applications. Gamma ray shows<br>
The more important while dealing with products in industrial applications. Gamma ray shows<br>
erty in surface charge decay rate. Howe **Surface Surface Surface Surface point of the Surface potential**<br> **Surface potential**<br> **Surface potential**<br> **Surface potential**<br> **Surface potential**<br> **Surface potential**<br> **Cat 1006s**<br> **Cat 1006s**<br> **Cat 1006s**<br> **Cat 1006s**<br> **Flashover voltage**<br> **Flashover voltage**<br> **Flashover voltage**<br> **Flashover voltage**<br> **Flashover voltage**<br> **KV**<br> **(Increasing rate)** 

|                   |         |                                   |   | <b>Result</b>                                    |   |   |  |
|-------------------|---------|-----------------------------------|---|--|---|---|--|
| Research<br>group | No./ref | <b>Treatment</b><br>method        | Parameter   | <b>Surface</b><br>conductivity<br>$10^{-18}$ S/m | <b>Surface potential</b><br>decay ratio<br>(at 1000s)   | <b>Flashover voltage</b><br>kV<br>(Increasing rate) |  |
|                   |         | gamma-ray<br>irradiation          | Untreated   |  | $7\%$   |   |  |
| Y. Gao<br>$[47]$  |         |                                   | 100kGy irradiation  |  | 10%   |   |  |
|                   |         |                                   | 1000kGy irradiation   |  | 15%   |   |  |
| J. Xue            |         | Surface<br>roughness<br>treatment | Roughness:0.58µm  | 5.8  |   | 15.5  |  |
|                   | $[85]$  |                                   | Roughness: 5.19µm   | 80.6   |   | $16.2 (+4.91\%)$                                    |  |
|                   |         |                                   | Roughness: 7.48µm   | 99.0   |   | $16.8 (+8.27%)$                                     |  |
|                   |         |                                   | Roughness: 9.24um   | 22.3   |   | $17.6$ ( +13.37%)                                   |  |
| D. Min            |         |                                   | Untreated   | 1100   | 20%   | 21.5  |  |
|                   | $[49]$  | Ozone                             | Processing 2h   | 25000  | 100%  | $24.7 (+14.88\%)$                                   |  |
|                   |         | treatment                         | Processing 4h   | 90000  | 100%  | $26.0 (+20.93\%)$                                   |  |
|                   |         |                                   | 4. Dam reinforcement-suppressing charge from volume conduction and gas ionization |  | In order to decrease the conduction current from the volume, manners of coating or doping are usually |   |  |

1. Xue [85] roughness  $\frac{1}{\text{Roughness}}$  Roughness 7.48 am  $\frac{1}{22.3}$  and  $\frac{1}{22.3}$  D. Min [49]  $\frac{\text{Ozone}}{\text{Precessing 2h}}$   $\frac{\text{Untracted}}{\text{Precessing 2h}}$  25000 100%<br> **4. Dam reinforcement-suppressing charge from volume conduction and gas ion**<br>
In order to decrease the conduction current from the volume, manners of coa<br> Frocessing and **4.1. Dam reinforcement-suppressing charge from volume conduction and gas ionization**<br>In order to decrease the conduction current from the volume, manners of coating or<br>used, while coating on the conductor In order to decrease the conduction current from the volume, manners of coating or doping are usually al, while coating on the conductor surface and/or smoothing the conductor surface both can decrease micro harge and ther

property.

AUTHOR SUBMI<br>4.1.1  $Cr_2O_3$  coating<br>A dense, ordered  $Cr_2O_3$  nano-coating c A dense, ordered Cr<sub>2</sub>O<sub>3</sub> nano-coating created by the magnetron sputtering method on the epoxy surface<br>A dense, ordered Cr<sub>2</sub>O<sub>3</sub> nano-coating created by the magnetron sputtering method on the epoxy surface<br>verified as a AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 26 of 54<br>4.1.1 Cr<sub>2</sub>O<sub>3</sub> coating<br>A dense, ordered Cr<sub>2</sub>O<sub>3</sub> nano-coating created by the magnetron sputtering method on the epoxy surface<br>was verified as a good way to restr AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 26 of 54<br>4.1.1 Cr<sub>2</sub>O<sub>3</sub> coating<br>A dense, ordered Cr<sub>2</sub>O<sub>3</sub> nano-coating created by the magnetron sputtering method on the epoxy surface<br>was verified as a good way to rest AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 26 of 54<br>4.1.1 Cr<sub>3</sub>O<sub>3</sub> coating<br>A dense, ordered Cr<sub>2</sub>O<sub>3</sub> nano-coating created by the magnetron sputtering method on the epoxy surface<br>was verified as a good way to restr 4.1.1 Cr<sub>2</sub>O<sub>3</sub> coating<br>A dense, ordered Cr<sub>2</sub>O<sub>3</sub> nano-coating created by the magnetron sputtering method on the epoxy surface<br>was verified as a good way to restrain charge injection from metal/insulation interface, whic [33].



E<br>
Fluorinated<br>
E<br>
Fluorinated<br>
Contract of entry of the surface-modified silica nanoparticles can be used to suppress the leakage<br>
E<br>
Z. Zhang *et al.* verified that surface-modified silica nanoparticles can be used to su Fluorinated<br> **Cross Equipment of example 21.** Surface potential increment from 0.5 min to 2 min [33].<br>
4.1.2 Nano-doping<br>
Z. Zhang *et al.* verified that surface-modified silica nanoparticles can be used to suppress the l o. 2. *Surface potential increment from 0.5 min to 2 min* [33].<br>
4.1.2 Nano-doping<br> *Z. Zhang et al.* verified that surface-modified silica nanoparticles can be used to suppress the leakage<br>
current of epoxy [86]. Figure **Figure 21.** Surface potential increment from 0.5 min to 2 min [33].<br>
4.1.2 Nano-doping<br>
Z. Zhang *et al.* verified that surface-modified silica nanoparticles can be used to suppress the leakage<br>
current of epoxy [86]. Fi 4.1.2 Nano-doping<br>
Z. Zhang *et al.* verified that surface-modified silica nanoparticles can be used to suppress the leakage<br>
current of epoxy [86]. Figure 22 presents the variation of volume conductivity (pv) of epoxy na 2. Zhang *et al.* verified that surface-modified silica nanoparticles can be used to suppress the leakage current of epoxy [86]. Figure 22 presents the variation of volume conductivity ( $\rho v$ ) of epoxy nanocomposites with Z. Zhang *et al.* verified that surface-modified silica nanoparticles can be used to suppress the leakage current of epoxy [86]. Figure 22 presents the variation of volume conductivity (pv) of epoxy nanocomposites with di eurrent of epoxy [86]. Figure 22 presents the variation of volume conductivity ( $\rho v$ ) of epoxy nanocomposites<br>with different filler fraction and the results show that for the non-linear change of the volume conductivity ( with different filler fraction and the results show that for the non-linear change of the volume conductivity (pv)<br>of the alkyl-modified nanoparticles with the proportion of filler, the maximum pv value is obtained at a lo of the alkyl-modified nanoparticles with the proportion of filler, the maximum<br>filling fraction (1wt%). They believed that the effect of the volume resistivity<br>nanoparticles can be attributable to two possible reasons: (1)



**Example carriers in the material [52].** They found that the electrical conductivity of 100ppm C<sub>60</sub> /<br>
example carriers in the material [52]. They found that the electrical conductivity of 100ppm C<sub>60</sub> /<br>
epoxy composite Figure 22. The volume resistivity (pv) of epoxy and epoxy nanocomposites at room temperature pv–filler<br>Figure 22. The volume resistivity (pv) of epoxy and epoxy nanocomposites at room temperature pv–filler<br>fraction curves Figure 22. The volume resistivity (pv) of epoxy and epoxy nanocomposites at room temperature pv–filler<br>fraction curves [86].<br>G. Zhang *et al.* introduced different contents of Buckminster-fullerene C<sub>60</sub> into epoxy resin Figure 22. The volume resistivity ( $\rho v$ ) of erfraction curves [86].<br>
G. Zhang *et al.* introduced different cont<br>
mobility of charge carriers in the material [5]<br>
epoxy composite decreases dramatically with<br>
conductivity The above mentioned studies focused on methods to suppress charge injection. However, S. He *et al.*<br>
The above mentioned studies for a value of  $1.0 \times 10^{-18}$ S / cm, which does not exceed 20% of the sultivity for pure ep G. Zhang *et al.* introduced different contents of Buckminster-fullerene  $C_{60}$  into epoxy resin to limit the mobility of charge carriers in the material [52]. They found that the electrical conductivity of 100ppm  $C_{60}$ 

mobility of charge carriers in the material [52]. They found that the electrical conductivity of 100ppm  $C_{60}$  /<br>epoxy composite decreases dramatically with a value of  $1.0 \times 10^{-18}$ S / cm, which does not exceed 20% of t epoxy composite decreases dramatically with a value of  $1.0 \times 10^{-18}$ S / cm, which does not exceed 20% of the conductivity for pure epoxy resin. They believe that deep traps introduced are responsible for the inhibition o conductivity for pure epoxy resin. They believe that deep traps introduced are responsible for the inhibition of<br>charge injection.<br>The above mentioned studies focused on methods to suppress charge injection. However, S. H charge injection.<br>The above mentioned studies focused on methods to suppress charge injection<br>focused on restraining the charge transport inside the bulk by doping  $K_2Ti_6O_{13}$  wh<br>material [53]. They took advantage of th The above member statues focused on memous to<br>focused on restraining the charge transport inside the bu<br>material [53]. They took advantage of the thermal barrier of<br>of homo-polar charges in the bulk, and the result demons ET EV TO EV TO EXERT UP TO USE THE USIDE THE USE THE USE OF SATISON USIDENT AND THE USE ON A USE THE USE ON A USE THE USE ON THE CHOIN SPACE IN A USE SECTION USIDENT SCALE SAMPLET SHOWER STANDARY CONDUCT THE SAMPLET SHOWE

of homo-polar charges in the bulk, and the result demonstrate that the introducing the K<sub>2</sub>Ti<sub>6</sub>O<sub>13</sub> whiskers can<br>effectively restrain heat propagation due to its excellent thermal barrier property, which in turn limits effectively restrain heat propagation due to its excellent thermal barrier property, which in turn limits charge<br>transport effectively, especially at temperature gradient.<br>4.1.3. Analysis and discussion<br>It has been shown transport effectively, especially at temperature gradient.<br>4.1.3. Analysis and discussion<br>It has been shown that  $C_{60}$  and  $SiO_2$  nano-fillers can reduce the sample volume conductivity. As shown in<br>the Table 6, the best 4.1.3. Analysis and discussion<br>It has been shown that  $C_{60}$  and  $SiO_2$  nano-fillers can reduce the sample ve<br>the Table 6, the best property of epoxy samples are obtained when the dopin<br>and  $SiO_2$  filler are 100 ppm and





G. Zhang [52] Nano-disping EpoxyAJO,  $20-25$   $\frac{246 \text{pm}}{200 \text{pm}}$   $\frac{100}{100}$   $\frac{6.9}{200}$   $\frac{10.9}{200 \text{pm}}$   $\frac{6.9}{200 \text{pm}}$   $\frac{6.9}{200 \text{pm}}$   $\frac{6.9}{200 \text{pm}}$   $\frac{6.9}{200 \text{pm}}$   $\frac{6.9}{200 \text{pm}}$   $\frac{6.9}{200 \text{pm}}$ S. He [53] Micron Epoxy/AlO, 1990 12-14 10% 1600pm 6.<br>
S. He [53] Micron Epoxy/AlO, VarTuO<sub>13</sub> 12-14 10% 96.15<br> **4.2 Suppressing charge from gas phase**<br>
The electric field at the micro-protrusions on the rough electrode s s. He [53] doping  $\frac{1-\text{poyy/Al_2O/wb} \cdot \text{Si_2O}}{10\%}$  = 12-14 10% 961.5<br>4.2 Suppressing charge from gas phase<br>The electric field at the micro-protrusions on the rough electrode surface can be enhanced to a level<br>under w 4.2 Suppressing charge from gas phase<br>
The electric field at the micro-protrusions on the rough electrode surface can be enhanced to a level<br>
under which micro-discharge will take place. Controlling the surface roughness The electric field at the micro-protrusions on the rough electrode surface can be enhanced to a level<br>under which micro-discharge will take place. Controlling the surface roughness of electrodes can effectively<br>suppress t The electric field at the micro-protrusions on the rough electrode sur<br>under which micro-discharge will take place. Controlling the surface rough<br>suppress the source of charge generated by the micro-discharge from the gas



*Dredging* is a commonly used approach to increase the canal depth and therefore increase the capacity of all is to commonly used approach to increase the canal depth and therefore increase the capacity of all is a common **Example 1.1E-14**  $\frac{1}{6}$  5  $\frac{1}{10}$  15  $\frac{20}{25}$  28  $\frac{30}{30}$ <br> **Electric field (kVmm)**<br>
20 °C, RH  $\approx$  30%) (a) in positive polarity;(b) in negative polarity [88].<br>
5. **Dredging-local electric field modification** Electric field (kV/mm)<br>
Electric field for three different electrode roughnesses, (0.6MPa,<br>
20 °C, RH  $\approx$  30%) (a) in positive polarity;(b) in negative polarity [88].<br>
5. Dredging-local electric field modification<br> *Dred* Figure 23. Current measured in SF<sub>6</sub>, versus electric field for three different electrode roughnesses, (0.6MPa, 20 °C, RH  $\approx$  30%) (a) in positive polarity;(b) in negative polarity [88].<br>
5. Dredging-local electric field modification of insulators can also be a good way to optimize local electric fields.<br>
S. Dredging is a commonly used approach to increase the canal depth and therefore increase the capacity of canals for carrying water. Wi *Dredging* is a commonly used approach to increase the canal c<br>canals for carrying water. With respects to spacers, by means of n<br>local electric field can be optimized and the flashover withstand vo<br>To achieve this goal, n In 1999, F. Messerer *et al.* coated dupont conductive powder the DC voltage of the spacer can thereby be increased.<br>
Scheieve this goal, nonlinear materials are usually adopted to modify the local electric field, and shap

on the surface of epoxy resin. They found that the maximum value of the spacer can thereby be increased.<br>To achieve this goal, nonlinear materials are usually adopted to modify the local electric field, and shape<br>modificat To achieve this goal, nonlinear materials are usually adopted to modify the local electric field, and shape<br>modification of insulators can also be a good way to optimize local electric fields.<br>**5.1. Nonlinear Conductive c** modification of insulators can also be a good way to optimize local electric fields.<br>
5.1. **Nonlinear Conductive composite**<br>
In 1999, F. Messerer *et al.* coated dupont conductive powder which contains titanium oxide and 5.1. Nonlinear Conductive composite<br>In 1999, F. Messerer *et al.* coated dupont conductive powder which contains titanium oxide and tin oxide<br>on the surface of epoxy resin. They found that the maximum value of the electr In 1999, F. Messerer *et al.* coated dupont conductive powder which contains titanium oxide and tin oxide<br>on the surface of epoxy resin. They found that the maximum value of the electric field on the surface of the<br>insula

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 30 of 54<br>distributed conductivities, nonlinear conductivity composites, which have nonlinear behavior with respect to<br>the electric field, are considered by researchers worl AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 30 of 54<br>distributed conductivities, nonlinear conductivity composites, which have nonlinear behavior with respect to<br>the electric field, are considered by researchers worl AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>distributed conductivities, nonlinear conductivity composites, which have nonlinear behavior<br>the electric field, are considered by researchers worldwide. This chapter mainly rev AUTHOR SUBMITTED<br>distributed conductivities, nonlinear conductivity<br>the electric field, are considered by researchers<br>nonlinear materials in the modification of local ele<br>5.1.1 Bulk doping<br>In 2013, M. Tenzer *et al.* propo buted conductivities, nonlinear conductivity composites, which have nonlinear behavior with respect to<br>lectric field, are considered by researchers worldwide. This chapter mainly reviews the application of<br>near materials i

Extra considerations, included the considerative procedure of the electric fields.<br>
S.1.1 Bulk doping<br>
In 2013, M. Tenzer *et al.* proposed an insulator using oriented "MFF (Minatec® functional filler)" filler<br>
192, 93]. T In steel and the modification of local electric fields.<br>
5.1.1 Bulk doping<br>
In 2013, M. Tenzer *et al.* proposed an insulator using oriented "MFF (Minatec® functional filler)" filler<br>
[92, 93]. These commercially available 1.1.1 Bulk doping<br>
In 2013, M. Tenzer *et al.* proposed an insulator using oriented "MFF (Minatec® functional filler)" filler<br>
1.1.1 Bulk doping<br>
1.1.1 Bulk doping<br>
1.1.1 Bulk doping<br>
1.1.1 Bulk doping<br>
1.1.1 Bulk doping<br> 5.1.1 Bulk doping<br>In 2013, M. Tenzer *et al.* proposed an insulator using oriented "MFF (Minatec® functional filler)" filler<br>[92, 93]. These commercially available particles are flake-shaped mica pigments, covered by a thi In 2013, M. Tenzer *et al.* proposed an insulator using oriented "MFF (Minatec® functional filler)" filler<br>[92, 93]. These commercially available particles are flake-shaped mica pigments, covered by a thin tin oxide<br>layer spacer.



AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>with their values of 8, 2.8 and 2 kV/mm for samples with doping ratios of 3, 10 and 14 vol% as shown in<br>Figure 25(a) [63]. They further found that with the increase of temperatu Figure 25(a) [63]. They further found that with the increase of temperature, the flashover voltage of untreated samples becomes higher than SiC-doped samples, as shown in Figure 25 (b), (c) and (d) [65]. samples becomes higher than SiC-doped samples, as shown in Figure 25 (b), (c) and 14 vol% as shown in Figure 25(a) [63]. They further found that with the increase of temperature, the flashover voltage of untreated samples





AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 32 of 54<br>Surprisingly, an opposite trend was reported regarding insulators doped with SiC [66]. As shown in Figure<br>the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone typ 26, the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone type insulators doped with SiC [66]. As shown in Figure 26, the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone type insulators and post type insulators with diff AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 32 of 54<br>Surprisingly, an opposite trend was reported regarding insulators doped with SiC [66]. As shown in Figure<br>26, the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone AUTHOR SUBMITTED MA<br>
Surprisingly, an opposite trend was reported rega<br>
26, the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of c<br>
SiC contents has descending trend, except for cone ty<br>
5.1.2 Surface coating<br>
ZnO is deposited

Surprisingly, an opposite trend was reported regarding insulators doped with SiC [66]. As shown in Figure<br>the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone type insulators and post type insulators with different<br>conten Surprisingly, an opposite trend was reported regarding insulators doped with SiC [66]. As shown in Figure 26, the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone type insulators and post type insulators with different S 26, the DC flashover voltage at 0.4 MPa SF<sub>6</sub> gas of cone type insulators and post type insulators with different<br>SiC contents has descending trend, except for cone type insulator with doping ratios of 20% and 25%.<br>5.1.2 SiC contents has descending trend, except for cone type insulator with doping ratios of 20% and 25%.<br>
5.1.2 Surface coating<br>
ZnO is deposited on epoxy surface by a magnetron sputtering to prepare functional gradient surf 5.1.2 Surface coating<br>
ZnO is deposited on epoxy surface by a magnetron sputtering to prepare functional gradient surface layer<br>
[64] and the surface flashover voltage was improved significantly. Subsequently, the concept 2.1.2 sunace coating<br>
[64] and the surface flashover voltage was improved significantly. Subsequently, the concept of the interfacial<br>
electric field self-regulating (IER) insulator was put forward and the tapered insulat ZnO is deposited on epoxy surface by a magnetron sputtering to prepare functional gradient surface layer [64] and the surface flashover voltage was improved significantly. Subsequently, the concept of the interfacial ele [64] and the surface flashover voltage was improved significantly. Subsequently, the concept of the interfacial<br>electric field self-regulating (IER) insulator was put forward and the tapered insulator with EP/SiC composit electric field self-regulating (IER) insulator was put forward and the tapered insulator with EP/SiC composite<br>material was prepared as the IER insulator [67]. β-SiC ring-clad insulators with different doping contents<br>(15 27(b)).



Examples are displayed in Figure 28 [68]. With the increase of SiC content, surface charges show firstly and increasing and then a decreasing trend.<br>
The increasing and then a decreasing trend.<br>
The increasing and then a Figure 27. (a) Measured flashover voltages of the conventional insulated contents and (b) leakage current and loss power of the IER insulators with Apart from that, J. Xue *et al.* sprayed a non-linear conductive coating



Figure 28. Surface charge distribution patterns with different SiC contents [68].<br>
As an example for the positive flashover test in air at 0.1MPa, the positive flashover voltage is<br>
non-linearly distributed by increasing  $\frac{20}{20}$  Figure 28. Surface charge distribution patterns with different SiC contents [68].<br>
As an example for the positive flashover test in air at 0.1MPa, the positive flashover voltage is<br>
non-linearly distributed by Figure 28. Surface charge distribution patterns with different SiC contents [68].<br>
As an example for the positive flashover test in air at 0.1MPa, the positive flashover voltage is<br>
non-linearly distributed by increasing



[69].

Then J. Xue *et al.* turned their attention to the influence of SiC particle size in SiC/epoxy coating [70]. As<br>
which is interested in SiC/epoxy coated shapes in SiC/epoxy coating [70]. As<br>
when in Figure 30, the results Figure 29. Surface flashover in 0.1MPa air on SiC/epoxy coated stage<br>
Figure 29. Surface flashover in 0.1MPa air on SiC/epoxy coated spacers with different SiC mass fractions<br>
[69].<br>
Then J. Xue *et al.* turned their atte E<sup>44</sup> Description of SiC fillers, the mass fraction of SiC fillers (%w)<br> **Figure 29.** Surface flashover in 0.1MPa air on SiC/epoxy coated spaces with different SiC mass fractions<br>
[69].<br>
Then J. Xue *et al.* turned their Figure 29. Surface flashover in 0.1MPa air on SiC/epoxy coated spacers with different (%w)<br>
[69].<br>
Then J. Xue *et al.* turned their attention to the influence of SiC particle size in SiC/epoxy solutions in Figure 30, the





shows that HV-coating has the best effect in increasing of surface flashover voltage.<br>
Shows that HV-coating locates at the middle of spacer surface (SPM-coating locates close to GND electrode (GND-coating). (d) High condu



nano-particles. With the SiC particles doping, shallow traps were introduced, leading to an evidently decline<br>of trap energy level, which would be beneficial to the process of charge de-trapping and extraction.<br>4.0x10<sup>21</sup> Example of HV-coating CND-coating SPM-coating HV-GND-coating<br>Different surface conductivity gradient coating schemes<br>Figure 32. Surface flashover voltage with different SCGC schemes [9].<br>J. Tang *et al.* prepared epoxy ma



E 8.0x10<sup>or</sup><br>  $0.8$  0.9 1.0 1.1 1.2<br>
Trap Level (eV)<br> **Figure 33**. Surface trap distribution of nano-SiC/Epoxy composites [71].<br>
3 Analysis and discussion<br>
In this section we chose representative results from the above me and discussion. Table 7 summarizes the effect of non-linear conductive composites [71].<br>
and discussion. Table 7 summarizes the effect of non-linear conductive composite modifications on the surface potential decay rate a Figure 33. Surface trap distribution of nano-SiC/Epoxy composites [71].<br>
5.1.3 Analysis and discussion<br>
In this section we chose representative results from the above mentioned research groups for comparison<br>
and discussio

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 36 of 54<br>
range of parameters including shape of sample, processing method, test environment, doping amount and<br>
applied voltage could directly influence on the results. In AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 36 of 54<br>
range of parameters including shape of sample, processing method, test environment, doping amount and<br>
applied voltage could directly influence on the results. In AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 36 of 54<br>
range of parameters including shape of sample, processing method, test environment, doping amount and<br>
applied voltage could directly influence on the results. In AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 36 of 54<br>
range of parameters including shape of sample, processing method, test environment, doping amount and<br>
applied voltage could directly influence on the results. In AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 36 of 54<br>
range of parameters including shape of sample, processing method, test environment, doping amount and<br>
applied voltage could directly influence on the results. In range of parameters including shape of sample, processing method, test environment, doping amount and applied voltage could directly influence on the results. In literature [63], a direct relationship between doping amount range of parameters including shape of sample, processing method, test environment, doping amount and applied voltage could directly influence on the results. In literature [63], a direct relationship between doping amoun applied voltage could directly influence on the results. In literature [65], a direct relationship between doping<br>amount and surface potential decay rate which shows increase of the doping rate for square sheet sample and<br> amount and surrace potential decay rate which shows increase of the doping rate for square sheet sample and under positive applied voltage leads to surface potential decay rate enhancement was presented, however, this rela inder positive applied voltage leads to surface potential decay rate emancement was presented, nowever, this<br>relation for disc sheet samples and under negative voltage can not be seen. Literature [65] shows that<br>temperatur relation for disc sneet samples and under negative voltage can not be seen. Literature [65] shows that<br>temperature rise increases the rate of surface potential decay for the same doping amount except for 14 %<br>doping at 70 depring at 70 °C. Moreover, the presented results in [67] describes the flashover voltage enhancement with the<br>doping at 70 °C. Moreover, the presented results in [67] describes the flashover voltage enhancement with the<br>g insulator. wth of doping amount for conventional insulator. Zhang *et al.* investigated the doping amount from 0 to % for cone type spacer and coating processing and the results show the maximum flashover voltage pens at 10 % doping. 50 % for cone type spacer and coating processing and the results show the maximum flashover voltage<br>happens at 10 % doping. Literature [66] studied the flashover voltage for different doping amount from 0 to<br>30 % for two t

happens at 10 % doping. Literature [66] studied the flashover voltage for different doping amount from 0 to 30 % for two types of samples including post type and cone type insulator; for post type insulators, doping decrea 30 % for two types of samples including post type and cone type insulator; for post type insulators, doping decreases the flashover voltage, yet 25 % doping causes 4.6 % growth of the flashover voltage for cone type insula decreases the flashover voltage, yet 25 % doping causes 4.6 % growth of the flashover voltage for cone type<br>insulator.<br>Meanwhile, regarding the surface flashover voltage at different temperatures, the temperature dependent insulator.<br>
Meanwhile, regarding the surface flashover voltage at different temperatures, the temperature dependent<br>
conductivity should be very important since it affects the charge decay rate significantly, resulting in Meanwhile, regarding the surface flashover voltage at different temperatures, the temperature dependent<br>conductivity should be very important since it affects the charge decay rate significantly, resulting in a<br>changing th conductivity should be very important since it affects the charge decay rate significantly, resulting in a<br>changing the surface flashover dispersion. However, problems lie in the difficulty of measuring the surface<br>conduct changing the surface flashover dispersion. However, problems lie in the difficulty of measuring the surface<br>conductivity at high field and high temperatures since surface flashover would be triggered even at very low<br>field conductivity at high field and high temperatures since surface flashover would be triggered even at very field (i.e. 30 kV/mm), during surface conductivity measurement, even for well protected and policelectrodes. Meanwhil



 $\begin{array}{|l|l|}\n\hline\n\text{loop} & \text{long} \\
\hline\n\text{loop} & \text{long} \\
\hline\n\text{non-type} & \text{long} \\
\hline\n\text{non-loop} & \text{long} \\
\hline\n\text$ **Example accumulation and realize local field improvement.** Apart from introducing nonlinear materials which modifies local electric field decently, modifying the profile of insulator to adjust the electric field line dis **Example 1998**<br> **Example improvement**<br> **Example improvement**<br> **Example in the above associated with a particular nearby source [2], and he believed that the overall geometry of<br>
the misulator would be associated with a pa** 5.2. Shape improvement<br>Apart from introducing nonlinear materials which modifies local electric field decently, modifying the<br>profile of insulator to adjust the electric field line distributions can also be a useful approa

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 38 of 54<br>papers [57, 95]. Since Cooke's 1982 paper, the surface charge accumulation phenomenon has been highlighted<br>by researchers using different model spacers. AUTHOR SUBMITTED MANUSCRIPT - NANO-1272<br>papers [57, 95]. Since Cooke's 1982 paper, the surface charge accumulation<br>by researchers using different model spacers.<br>5.2.1. Literature review AUTHOR SUBMITTED MANUS<br>
papers [57, 95]. Since Cooke's 1982 paper, the surface che<br>
by researchers using different model spacers.<br>
5.2.1. Literature review<br>
In 1983, a very detailed study on surface chargin

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 38 of 54<br>
Page 38 of 54<br>
I. Literature cooke's 1982 paper, the surface charge accumulation phenomenon has been highlighted<br>
Esearchers using different model spacers.<br>
I. Li papers [57, 95]. Since Cooke's 1982 paper, the surface charge accumulation phenomenon has been highlighted<br>by researchers using different model spacers.<br>5.2.1. Literature review<br>In 1983, a very detailed study on surface ch papers [57, 95]. Since Cooke's 1982 paper, the surface charge accumulation phenomenon has been highlighted<br>by researchers using different model spacers.<br>5.2.1. Literature review<br>In 1983, a very detailed study on surface c



 $\begin{array}{c|c}\n\hline\n\end{array}$ <br>  $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$   $\begin{array}{c}\n\hline\n\end{array}$ progress in exploring the surface charge transport in real-sized spacers accelerates the research<br>progress in exploring the surface charge transport in real-sized spacers accelerates the research<br>progress in exploring the **Examplemental**<br> **Examplemental application of surface charge transport in real-sized spacers accelerates the research<br>
progress in exploring the surface charge transport in real-sized spacers accelerates the research<br>
pr** Figure 34. Spacer model designed by Fujinami [56].<br>
Figure 34. Spacer model designed by Fujinami [56].<br>
After 1988, the investigation of surface charge transport in real-sized spacers accelerates the research<br>
progress in Figure 34. Spacer model designed by Fujinami [56].<br>
After 1988, the investigation of surface charge transport in real-sized spacers accelerates the research<br>
progress in exploring the surface charge transport mechanism [54 Figure 34. Spacer model designed by Fujinami [56].<br>
After 1988, the investigation of surface charge transport in real-sized spacers accelerates the research<br>
progress in exploring the surface charge transport mechanism [54 After 1988, the investigation of surface charge transport in real-sized spacers accelerates the research<br>progress in exploring the surface charge transport mechanism [54, 55]. However, the implementation of<br>industrial app progress in exploring the surface charge transport mechanism [54, 55]. However, the industrial application of HVDC spacers has still been hampered by the non-reproduction and difficulties in interpreting the surface charge





Figure 36. Distributions of electric field and its components on spacer surface concave side. (a) Disc-basin<br>
Figure 36. Distributions of electric field and its components on spacer surface concave side. (a) Disc-basin<br>
P Figure 36. Distributions of electric field and its components on spacer surface concave side. (a) Disc-basin spacer, (b) cone-basin spacer, and (c) half conical-basin spacer [59].<br>
Figure 36 shows the combined field stren **It can be found that the** *En* of the semi-conical basin insulator is lower than that of the conical insulator, which can be found that the *En* of the semi-conical basin insulator is lower than that of the conical insul Figure 36. Distributions of electric field and its components on spacer surface concave spacer, (b) cone -basin spacer, and (c) half conical-basin spacer [59].<br>Figure 36 shows the combined field strength E, field strength Distance *D*<br>
In 2004, Distributions of electric field and its components on spacer surface concave side. (a) Disc-basin<br>
Eigure 36 shows the combined field strength *E*, field strength tangential component *Et* and field gas insulation systems [60], and proposed generalized design criteria for HVDC insulators. He believed that the believed that proposed generalized design of a 500 kV DC GIS bus in 1997 [59].<br>It can be found that the *En*

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 40 of 54<br>the first principle for the optimal design of columnar insulation structures is that the maximum value of the<br>electric field strength along the insulator is smalle AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 40 of 54<br>the first principle for the optimal design of columnar insulation structures is that the maximum value of the<br>electric field strength along the insulator is smalle AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 40 of 54<br>the first principle for the optimal design of columnar insulation structures is that the maximum value of the<br>electric field strength along the insulator is smalle AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 40 of 54<br>the first principle for the optimal design of columnar insulation structures is that the maximum value of the<br>electric field strength along the insulator is smalle AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 40 of 54<br>the first principle for the optimal design of columnar insulation structures is that the maximum value of the<br>electric field strength along the insulator is smalle the first principle for the optimal design of columnar insulation structures is that the maximum value of the<br>electric field strength along the insulator is smaller than the insulation margin. In this basic principle, the<br>



Figure 37. Three different shapes of insulators [62].<br>
The discreption of the material and shape of the insulator on its<br>
Tashover characteristics under DC voltage. Figure 37 shows insulators with different shapes used for Experimental comparison [62]. The result showed that the flashover voltage of the umbrella skirt insulator on its flashover characteristics under DC voltage. Figure 37 shows insulators with different shapes used for experi Column<br>Column Conce<br>Figure 37. Three different<br>Z. Jia *et al.* focused on the comprehensive influence<br>flashover characteristics under DC voltage. Figure 37<br>experimental comparison [62]. The result showed that the<br>the highe In our recent research [61], a criterion was put forwordwhich focused on the balance of the insulators [62].<br>In our recent research in the comprehensive influence of the material and shape of the insulator on its hover cha Eigure 37. Three different shapes of insulators [62].<br>
Z. Jia *et al.* focused on the comprehensive influence of the material and shape of the insulator on its<br>
flashover characteristics under DC voltage. Figure 37 shows i Z. Jia *et al.* focused on the comprehensive influence of the marticular measuremental comparison [62]. The result showed that the flashover v the highest at each pressure.<br>In our recent research [61], a criterion was put



> 

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>The novel DC cone-type insulator passed a series of tests according to standards in gas-insulated<br>ipment [61], which provided a better performance than the traditional AC insula For a set of tests according to standards in gas-insulated<br>equipment [61], which provided a better performance than the traditional AC insulators in the same voltage<br>level. It is noted the flashover voltage of the novel i S4<br>
In a novel DC cone-type insulator passed a series of tests according to standards in gas-insulated<br>
equipment [61], which provided a better performance than the traditional AC insulators in the same voltage<br>
level. It Example 10 and HOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
The novel DC cone-type insulator passed a series of tests according to standards in gas-insulated<br>
equipment [61], which provided a better performance than the tra AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>The novel DC cone-type insulator passed a series of tests according to standards in gas-insulated<br>ipment [61], which provided a better performance than the traditional AC insul

The novel DC cone-type insulator passed a series of tests according to standards in gas-insulated<br>equipment [61], which provided a better performance than the traditional AC insulators in the same voltage<br>level. It is not The novel DC cone-type insulator passed a series of tests according to standards in gas-insulated<br>equipment [61], which provided a better performance than the traditional AC insulators in the same voltage<br>level. It is not equipment [61], which provided a better perfc<br>level. It is noted the flashover voltage of the ne<br>exceeded the evaluation standard. in the 1: 4 SF<br>Meanwhile, a  $\pm 200$  kV spacer as shown i<br>200kV dc spacer and a 220kV AC s ], which provided a better performance than the traditional AC insulators in the same of the flashover voltage of the novel insulator under DC superimposedlightning inply valuation standard. in the 1: 4 SF<sub>6</sub> / N<sub>2</sub> gas ditional AC insulators in the same voltage<br>DC superimposedlightning inpluse voltage,<br>t 0.7 Mpa.<br>urther developed. Comparison between the<br>rrface flashover and polarity reversal tests at<br>charge density of convex surface is level. It is noted the flashover voltage of the novel insulator under DC superinexceeded the evaluation standard. in the 1: 4 SF<sub>6</sub>/N<sub>2</sub> gas mixture at 0.7 Mpa.<br>Meanwhile, a  $\pm 200 \text{ kV}$  spacer as shown in Figure 39, wa here is surface to 18 μC/m<sup>2</sup> parameter and polarity reversal tests at in Figure 39, was further developed. Comparison between the sperformed by DC surface flashover and polarity reversal tests at C spacer, the surface ch exceeded the evaluation standard. in the 1: 4 SF<sub>6</sub>/N<sub>2</sub> gas mixture at 0.7 Mpa.<br>
Meanwhile, a  $\pm 200 \text{ kV}$  spacer as shown in Figure 39, was further developed. Comparison between the<br>
200kV dc spacer and a 220kV AC spa Meanwhile, a  $\pm 200$  kV spacer as shown in Figure 39, was further developed. Comparison between the 200kV dc spacer and a 220kV AC spacer was performed by DC surface flashover and polarity reversal tests at 0.3MPa SF<sub>6</sub> 200kV dc spacer and a 220kV AC spacer was performed by DC surface flashover and polarity reversal tests at 0.3MPa SF<sub>6</sub> (as shown in Figure 40). For DC spacer, the surface charge density of convex surface is lower than 10 0.3MPa SF<sub>6</sub> (as shown in Figure 40). For DC spacer, the surface charge density of convex surface is lower than 10 µC/m<sup>2</sup>, and that of concave surface is lower than 5 µC/m<sup>2</sup>. For AC spacer, the surface charge density of than 10  $\mu$ C/m<sup>2</sup>, and that of concave surface is lower than 5  $\mu$ <br>of concave surface is higher than 10  $\mu$ C/m<sup>2</sup>, and it even reflashover voltage of AC and DC spacers are both lower tha<br>voltage of AC spacer after pola





AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 42 of 54<br> **Figure 40.** (a) Time varying curves of surface charge density along the surface of AC and DC spacers after<br>
applying 240 kV voltage, and (b) surface flashover vo

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 42 of 54<br> **Figure 40.** (a) Time varying curves of surface charge density along the surface of AC and DC spacers after<br>
applying 240 kV voltage, and (b) surface flashover vo AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 42 of 54<br> **Figure 40.** (a) Time varying curves of surface charge density along the surface of AC and DC spacers after<br>
applying 240 kV voltage, and (b) surface flashover vo AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 42 of 54<br>
Figure 40. (a) Time varying curves of surface charge density along the surface of AC and DC spacers after<br>
applying 240 kV voltage, and (b) surface flashover volt AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 42 of 54<br> **Figure 40.** (a) Time varying curves of surface charge density along the surface of AC and DC spacers after<br>
applying 240 kV voltage, and (b) surface flashover vo Figure 40. (a) Time varying curves of surface charge density along the surface of AC and DC spacers after applying 240 kV voltage, and (b) surface flashover voltage test results at 0.3 MPa SF<sub>6</sub>.<br>One difficulty with gas-in **Figure 40.** (a) Time varying curves or stratee charge density along the surface or AC and DC spacers are applying 240 kV voltage, and (b) surface flashover voltage test results at 0.3 MPa SF<sub>6</sub>.<br>One difficulty with gas-i One difficulty with gas-insulated components under DC stress is to predict the field distribution in the solid spacers and in the gas in the vicinity of the spacers. DC spacers must be able to withstand not only long time solid spacers and in the gas in the vicinity of the spacers. DC spacers must be able to withstand not only long<br>time DC stress but also switching and lightning overvoltages and DC polarity reversal. All these factors have<br> time DC stress but also switching and lightning overvoltages and DC polarity reversal. All these factors have<br>to be considered when DC spacers are designed. There is therefore a need to develop methods to investigate<br>charg to be considered when DC spacers are designed. There is therefore a need to develop methods to investigate charge accumulation and field distributions on spacer surfaces. As a charging counter measure surface coating of in charge accumulation and field distributions on spacer surfaces. As a charging counter measure surface coating<br>of insulators was introduced for the first time. The spacers used were made of a standard epoxy with alumina<br>fil of insulators was introduced for the first time. The spacers used were made of a standard epoxy with alumina<br>filler. Some of the spacers have been covered with a slightly conducting film. The spacer surfaces were<br>cleaned w filler. Some of the spacers have been covered with a slightly conducting film. The spacer surfaces were cleaned with alcohol before mounting. This treatment gave charge-free surfaces. The potential shift for the covered sp cleaned with alcohol before mounting. This treatment gave charge-free surfaces. The potential shift for the covered spacers reached its equilibrium faster in a few days. After polarity reversal, the potential shift reverse covered spacers reached its equilibrium faster in a few days. After polarity reversal, the<br>reversed and reached steady state with the same time constant as before. In Figure 41 a summ<br>results for both coated and uncoated s



Another approach to avoid charge accumulation is to make the resistive field distribution equal or similar<br>he capactive field distribution by design and proper choice of material properties[56, 96-98]. The influence<br>empera AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>Another approach to avoid charge accumulation is to make the resistive field distribution equal or similar<br>to the capactive field distribution by design and proper choice of mat AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
Another approach to avoid charge accumulation is to make the resistive field distribution<br>
to the capactive field distribution by design and proper choice of material propertie AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>Another approach to avoid charge accumulation is to make the resistive field distribution equal or similar<br>the capactive field distribution by design and proper choice of materi

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
Another approach to avoid charge accumulation is to make the resistive field distribution equal or similar<br>
to the capactive field distribution by design and proper choice of m Another approach to avoid charge accumulation is to make the resistive field distribution equal or similar<br>to the capactive field distribution by design and proper choice of material properties[56, 96-98]. The influence<br>of Another approach to avoid charge accumulation is to make the resistive field distribution equal of similar<br>to the capactive field distribution by design and proper choice of material properties[56, 96-98]. The influence<br>of in the less conductive relationships of temperature distribution must be considered.<br>The magnitude of the electric field at the solid-gas insulation interface (gas side) for various ion densities<br>is shown in Figure 42. For The magnitude of the electric field at the solid-gas insulation interface (gas side) for various ion densities<br>is shown in Figure 42. For short times, the capacitive field (denoted AC) is tangential to the surface, result



Based on the research for material characterisation and the usage of multi-physics simulation tools the research for material characterisation and the usage of multi-physics simulation tools the size of electrical field d **Example 12.** Electrical field at the solid-gas interface for various ion production rates. Insets show field lines in the gas (white) and solid (red) with example of ion capture volume (yellow region) [99].<br>Based on the **Exercise 42.** Electrical field at the solid-gas interface for various ion production rates. Insets show field lines in the gas (white) and solid (red) with example of ion capture volume (yellow region) [99].<br>Based on the **Example 42.** Electrical field at the solid-gas interface for various ion production rates. Insets show field lines in the gas (white) and solid (red) with example of ion capture volume (yellow region) [99].<br>Based on the Figure 42. Electrical field at the solid-gas interface for various ion production rates. Insets show field lines in the gas (white) and solid (red) with example of ion capture volume (yellow region) [99].<br>Based on the res Figure 42. Encturiar field the solutions of production insulator (Figure 31) increases interest for warmple of ion capture volume (yellow region) [99].<br>Based on the research for material characterisation and the usage of Based on the research for material characterisation and the usage of multi-physics simulation tools the analysis of electrical field distribution is now possible with high precision, taking the following parameters into co



For the optimized HVDC design, the improvement shown with a significant reduction of the dielectric<br>sy was obtained by geometrical optimization and insertion of a current collector, compared to the AC<br>gn[102]. The tempera **Stress was obtained by geometrical optimization and insertion of a current collector, compared to the AC**<br>design[102]. The temperature gradient across the improvement shown with a significant reduction of the dielectric<br> **Example 102**<br> **Example 102**<br> **Example 102**<br> **Example 102**<br> **Example 102**<br> **Example 102**<br> **Example 102**<br>
Figure 43. Comparison between capacitive and steady-state resistive electric field strength distribution (gas<br>
side) **Example 13.** Comparison between capacitive and steady-state resistive electric field strength d<br>side) for the HVAC partition [101].<br>For the optimized HVDC design, the improvement shown with a significant reduction c<br>stres Figure 43. Comparison between capacitive and steady-s<br>side) for the HVAC partition [101].<br>For the optimized HVDC design, the improvement s<br>stress was obtained by geometrical optimization and ins<br>design[102]. The temperatur For the optimized HVDC design, the improvement shown with a significant reduction of the dielectric<br>ess was obtained by geometrical optimization and insertion of a current collector, compared to the AC<br>sign[102]. The tempe

stress was obtained by geometrical optimization and insertion of a current collector, compared to the AC<br>design[102]. The temperature gradient across the insulation considered for the simulation is equal to the worst<br>case design[102]. The temperature gradient across the insulation considered for the simulation is equal to the worst<br>case under service conditions and maximum continuous current.<br>5.2.2 Analysis and discussion<br>Shape modification case under service conditions and maximum continuous current.<br>
5.2.2 Analysis and discussion<br>
Shape modification as an approach to suppress surface charge accumulation of the insulator has advantages<br>
such as simple operat 5.2.2 Analysis and discussion<br>Shape modification as an approach to suppress surface charge accumulation of the insulator has advantages<br>such as simple operation process and high reliability, which is preferred by manufactu S.2.2 Anarysis and discussion<br>Shape modification as an approach to suppress surface charge accumulation of the insulator has advantages<br>such as simple operation process and high reliability, which is preferred by manufactu Shape modification as an approach to suppress surface charge accumulation of the insulator has advantages<br>such as simple operation process and high reliability, which is preferred by manufactures. The temperature<br>dependent such as simple operation process and high reliability, which is preferred by manufactures. The temperature<br>dependent conductivity may influence electric field distributions at DC, which results in irregular charge<br>behavior dependent conductivity may influence electric field distributions at DC, which results in irregular charge behaviors. This issue should be considered carefully. Currently, we see some favorable evidences regarding manufact behaviors. This issue should be considered carefully. Currently, manufacturing of HVDC spacers, as is discussed in [61, 101, 10 margin used for qualifying a charge density as well as a electric acceptable for the stable op manuacturing of HVDC spacers, as is discussed in [61, 101, 102], nowever, it is suif a pity that<br>margin used for qualifying a charge density as well as a electric field stress/normal component v<br>acceptable for the stable o

A novel design of HVDC spacer (shown in Figure 44) was introduced based on the concept of adaptively<br>trolling surface charges using nonlinear materials. This method, unlike commonly used traditional<br>roaches, proposed a nov A novel design of HVDC spacer (shown in Figure 44) was introduced based on the concept of adaptively<br>controlling surface charges using nonlinear materials. This method, unlike commonly used traditional<br>approaches, proposed A novel design of HVDC spacer (shown in Figure 44) was introduced based on the concept of adaptively<br>controlling surface charges using nonlinear materials. This method, unlike commonly used traditional<br>approaches, proposed AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
A novel design of HVDC spacer (shown in Figure 44) was introduced based on the concept of adaptively<br>
controlling surface charges using nonlinear materials. This method, unlike AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
A novel design of HVDC spacer (shown in Figure 44) was introduced based on the concept of adaptively<br>
controlling surface charges using nonlinear materials. This method, unlike A novel design of HVDC spacer (shown in Figure 44) was introduced based on the concept of adaptively<br>controlling surface charges using nonlinear materials. This method, unlike commonly used traditional<br>approaches, proposed







AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 46 of 54<br>Before choosing the charge tailoring methods, we should firstly clarify the charge type we were to deal<br>i, i.e. the homo-polarity charge due to conduction current AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 46 of 54<br>Before choosing the charge tailoring methods, we should firstly clarify the charge type we were to deal<br>with, i.e. the homo-polarity charge due to conduction curre AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 46 of 54<br>Before choosing the charge tailoring methods, we should firstly clarify the charge type we were to deal<br>with, i.e. the homo-polarity charge due to conduction curre AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 46 of 54<br>Before choosing the charge tailoring methods, we should firstly clarify the charge type we were to deal<br>with, i.e. the homo-polarity charge due to conduction curre AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>Before choosing the charge tailoring methods, we should firstly clarify the charge type w<br>with, i.e. the homo-polarity charge due to conduction current and/or the hetero-polarit Before choosing the charge tailoring methods, we should firstly clarify the charge type we were to deal<br>
i, i.e. the homo-polarity charge due to conduction current and/or the hetero-polarity charge from the gas.<br>
ler this Before choosing the charge tailoring methods, we should firstly clarify the charge type we were to deal<br>with, i.e. the homo-polarity charge due to conduction current and/or the hetero-polarity charge from the gas.<br>Under th

with, i.e. the homo-polarity charge due to conduction current and/or the hetero-polarity charge from the gas.<br>Under this premise, we can regulate the charge in a targeted manner. Recently published research proposes a<br>fair Under this premise, we can regulate the charge in a targeted manner. Recently published research proposes a fairly convincing field-dependent charging theory, as has already discussed in the introduction, which can serve a fairly convincing field-dependent charging theory, as has already discussed in the introduction, which can serve as a reference for ways determining charge origins [16].<br>
Based on the charge origins, this paper introduces serve as a reference for ways determining charge origins [16].<br>
Based on the charge origins, this paper introduces a Dam-flood model and classifies the surface charge<br>
tailoring methods proposed by different researchers. H Based on the charge origins, this paper introduces a Dam-flood model and classifies the surface charge tailoring methods proposed by different researchers. However, during chemically changing the surface conductivity, whic tailoring methods proposed by different researchers. However, during chemically changing the surface<br>conductivity, which has been verified to be an important way changing surface flashover voltage, the surface<br>morphology i conductivity, which has been verified to be an important way changing surface flashover voltage, the surface morphology is usually changed. This makes it difficult for us to discern what parameter plays a decisive role in morphology is usually changed. This makes it difficult for us to discern what parameter plays a decisive role<br>in surface flashover voltage improvement. For example, in the fluorination process, is it the morphology<br>optimi



modification.

Figure 46. Distribution range of the surface conductivity of epoxy based samples before and after surface<br>modification.<br>Figure 46. Distribution range of the surface conductivity of epoxy based samples before and after sur **Eigure 46.** Distribution range of the surface conductivity of epoxy based samples before and after surface modification.<br>
Figure 46. Distribution range of the surface conductivity of epoxy based samples before and after

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>modification increases surface conductivity and better surface property can be obtained. Further, we can see<br>that fluorination results in a surface conductivity ranging from 8.6 AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>modification increases surface conductivity and better surface property can be obtained. Further, we can see<br>that fluorination results in a surface conductivity ranging from 8. AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>modification increases surface conductivity and better surface property can be obtained. Further, we can see<br>that fluorination results in a surface conductivity ranging from  $8$ AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
modification increases surface conductivity and better surface property can be obtained. Further, we can see<br>
that fluorination results in a surface conductivity ranging from **EXECUTE ALTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1**<br> **Investigation** increases surface conductivity and better surface property can be obtained. Further, we can see<br>
that fluorination results in a surface conductivity lification increases surface conductivity and better surface property can be obtained. Further, we can see fluorination results in a surface conductivity ranging from 8.6×10<sup>-19</sup>S to 9×10<sup>-14</sup>S, which is relative lower ppa modification increases surface conductivity and better surface property can be obtained. Further, we can see<br>that fluorination results in a surface conductivity ranging from 8.6×10<sup>-19</sup>S to 9×10<sup>-14</sup>S, which is relative lo

that fluorination results in a surface conductivity ranging from  $8.6 \times 10^{-19}$ S to  $9 \times 10^{-14}$ S, which is relative lower<br>compared with plasma treatment. However, coatings introduce a surface conductivity up to  $1.11 \times 1$ compared with plasma treatment. However, coatings introduce a surface conductivity up to  $1.11 \times 10^{29}$ S which<br>is much higher compared with other surface modification methods. Surface roughness and ozone treatment<br>increas is much higher compared with other surface modification methods. Surface roughness and ozone treatment<br>increase surface flashover voltage while the trivial surface conductivity change is shown.<br>Such large difference over r increase surface flashover voltage while the trivial surface conductivity, to our knowledge, can be partially due to such large difference over results in surface conductivity, to our knowledge, can be partially due to dif Such large difference over results in surface conductivity, to our knowledge, can be partially due to differences in test setup and environment condition (i.e., air pressures, ambient gases), electrode arrangement, electri differences in test setup and environment condition (i.e., air pressures, ambient gases), electrode arrangement,<br>electric fields, etc.. Meanwhile, as a variable material which shows different properties produced by differe electric fields, etc.. Meanwhile, as a variable material which shows different properties produced by different<br>companies, epoxy resin may probably be another factor responsible for such variations in measurement results.<br> companies, epoxy resin may probably be another factor responsible for such variations in measurement results.<br>We would suggest that all tests and measurements to be based on practical industrial applications, and the test<br> We would suggest that all tests and measurements to be based on practical industrial applications, and the test<br>environmental condition should strictly follow the industrial application environment. In addition, there are<br> environmental condition should strictly follow the industrial application environment. In addition, there are<br>various methods for characterizing material properties, and there is still a lack of unified measurement<br>standar various methods for characterizing material properties, and there is still a lack of unified measurement<br>standards. Even if the same epoxy resin and the same processing technology are used, the conductivity<br>measured by eac standards. Even if the same epoxy resin and the same processing technology are used, the conductivity measured by each research group is different, and some are several orders of magnitude different. (For example, the untr measured by each research group is different, and some are several orders of magnitude different. (For example, the untreated epoxy conductivity measurement Z. An and G. Chen's group are different [19-21, 27, 28], and afte example, the untreated epoxy conductivity measurement Z. An and G. Chen's group are different [19-21, 27, 28], and after the same treatment method, the surface conductivity of fluorinated samples such as J. He and B.<br>Du ha 28], and after the same treatment method, the surface conductivity of fluorinated samples such as J. He and B.<br>Du have a greater difference [30-32]). Such dispersion makes it difficult to compare and evaluate the<br>effective Du have a greater difference [30-32]). Such dispersion makes it difficult to compare and evaluate the effectiveness of a certain treatment method, which hinders the selection of surface conductivity during the preparation effectiveness of a certain treatment method, which hinders the selection of surface conductiver<br>preparation of insulators operating under DC voltage. It is necessary that the same measuremer<br>conditions are selected to ensu preparation of insulators operating under DC vortage. It is in<br>conditions are selected to ensure replicability of tests to ob<br>the conductivity measurement guidelines proposed in [10]<br>extension of measurement time to 24h is

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 48 of 54<br>Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>researchers concerned more about. The transition of elec AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 48 of 54<br>Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>that researchers concerned more about. The transition of AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 48 of 54<br>Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>that researchers concerned more about. The transition of AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 48 of 54<br>Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>that researchers concerned more about. The transition of AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 48 of 54<br>Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>that researchers concerned more about. The transition of Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>that researchers concerned more about. The transition of electrons from the Fermi level to the conduction band<br>requ Regarding the all charge tailoring techniques mentioned in this work, resistivity and traps are parameters<br>that researchers concerned more about. The transition of electrons from the Fermi level to the conduction band<br>requ that researchers concerned more about. The transition of electrons from the Fermi level to the conduction band<br>requires energy to overcome the forbidden band whose width represents the resistivity of the polymer. When<br>the requires energy to overcome the forbidden band whose width represents the resistivity of the polymer. When<br>the polymer is modified either by surface modification or the volume doping, it is equivalent to introduce new<br>impu polymer is modified either by surface modification or the volume doping, it is equivalent to introduce new<br>urities whose energy levels locates intermittently between the Fermi level and the conduction band of the<br>mer. Unde impurities whose energy levels locates intermittently between the Fermi level and the conduction band of the<br>polymer. Under such case, when the electrons cross the forbidden band, the energy levels introduced by<br>impurities

polymer. Under such case, when the electrons cross the forbidden band, the energy levels introduced by<br>impurities serves as a 'step', and it will be easier for electrons to overcome the forbidden band before reaching<br>the c impurities serves as a 'step', and it will be easier for electrons to overcome the forbidden band before reaching<br>the conduction band. As a consequence, it can be conceived that the forbidden band becomes narrower and the<br> the conduction band. As a consequence, it can be conceived that the forbidden band becomes narrower and the trap density of the material becomes shallower, resulting in smaller resistivity [104].<br>As has been indicated by r trap density of the material becomes shallower, resulting in smaller resistivity [104].<br>As has been indicated by researchers that shallow traps increase surface charge decay, which is similar to<br>the effect of increasing su As has been indicated by researchers that shallow traps increase surface charge decay, which is similar to the effect of increasing surface conductivity. Meanwhile, it has been verified that a surface with higher conductiv the effect of increasing surface conductivity.<br>
conductivity facilitates surface charge decay is<br>
decays through bulk or/and recombination wit<br>
conductivity s used [105-107]. It should be emp<br>
charge injection as a manner conductivity facilitates surface charge decays through bulk or/and recombination<br>decays through bulk or/and recombination<br>conductivity s used [105-107]. It should be<br>charge injection as a manner to suppress<br>electrode/diele ctivity s used [105-107]. It should be emphasized that deep traps can only be effective to inhibition of<br>
injection as a manner to suppress surface charge accumulation in case they are being created in the<br>
de/dielectric i

charge injection as a manner to suppress surface charge accumulation in case they are being created in the<br>electrode/dielectric interface other than over the gas/solid interface-which prevents charge decay from<br>insulator s electrode/dielectric interface other than over the gas/solid interface-which prevents charge decay from<br>insulator surface.<br>**8. Conclusion**<br>This paper introduces a Dam model, based on which surface charge tailoring techniqu **8. Conclusion**<br>This paper introduces a Dam model, based on which surface charge tailoring techniques are classified<br>and reviewed in a manner of increasing surface charge decay, inhibiting homo-polar charges from volume<br>co 8. Conclusion<br>This paper introduces a Dam model, based on which surface charge tailoring techniques are classified<br>and reviewed in a manner of increasing surface charge decay, inhibiting homo-polar charges from volume<br>cond **Consideration**<br>This paper introduces a Dam model, based on which surface charge tailoring techniques are classified<br>and reviewed in a manner of increasing surface charge decay, inhibiting homo-polar charges from volume<br>co This paper introduces a Dam model, based on which surface charge tailoring techniques are classified<br>and reviewed in a manner of increasing surface charge decay, inhibiting homo-polar charges from volume<br>conduction, decayi and reviewed in a manner of increasing surface charge decay, inhibiting homo-polar charges from volume conduction, decaying/avoiding charges at high electric field, and initiatively controlling and decaying charges. Techni

AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>to industrial production should also be considered. Before successfully developing of charge-free insulators,<br>the progress and improvement in this field requires our joint effor AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>to industrial production should also be considered. Before successfully developing of charge-free insulators,<br>the progress and improvement in this field requires our joint effor AUTHOR SUBMITTED<br>to industrial production should also be consider<br>the progress and improvement in this field requ<br>treatment method.<br>Acknowledgement

## **Acknowledgement**

The Matuscher P-NANO-122263.ht<br>
industrial production should also be considered. Before successfully developing of charge-free insulators,<br>
progress and improvement in this field requires our joint efforts both in charge t 51677113). **Acknowledgement**<br> **(11)**<br> **Exercises**<br> Viedgement<br>work was supported in part by the National Natural Science Foundation of China (Grant 1<br>3).<br>compressed gas insulation *IEEE Transactions on Dielectrics and Electrical Insulation* 25 1152-66<br>Cooke C M 1982 Chargi This work was supported in part by the National Natural Science Foundation of China (Grant No.<br> **References**<br>
[1] Li C, Lin C, Zhang B, Li Q, Liu W, Hu J and He J 2018 Understanding surface charge accumulation and surface

### **References**

- 
- 172-8
- **Exercises**<br>
13 Li C, Lin C, Zhang B, Li Q, Liu W, Hu J and He J 2018 Understanding surface charge accumulation and surface flashover on spacers in<br>
13 cooke C M 1982 Charging of Insulator Surfaces by lonization and Transp **interface charge charge charge charge charge charge accumulation and surface flaments compressed gas insulation** *IEEE Transactions on Dielectrics and Electrical Insulation* **<b>25** 1152-66<br>Cooke C M 1982 Charging of Insulato External of C. Lin C, Zhang B, Li Q, Liu W, Hu J and He J 2018 Understanding surface charge accumulation and surface flashover on spacers in compressed gas insulation *IEEE Transactions on Dielectrical Insulation* 25 1152compressed gas insulation *IEEE Transactions on Dielectrics and Electrical Insulation* 25 1152-66<br>
[2] Cooke C M 1982 Charging of Insulator Surfaces by Ionization and Transport in Gases *IEEE Transactions on Electrical Ins* [6] Tanaka T 2005 Dielectric nanocomposites with insulating properties *IEEE Transactions on Electrical Insulation* **EI-17**<br>
172-8<br> **EXEC TRANGE TRANGE** 27 Ethnic, Li C, Suraci S, Chen G, Riechert U, Shahsavarian T, Hikita M, Tu Y, Zhang Z, Fabiani D and He J 2020 Gas-solid<br>
interface charge characterization techniques for HVDC GIS/GIL insulators *High Voltage*<br>
1997 A, De Zhang L, Lin C, Li C, Suraci S, Chen G, Riechert U, Shahsavarian<br>interface charge characterization techniques for HVDC GIS/GIL insulat<br>Dey A, De S, De A and De S K 2004 Characterization and dielectric<br>1277-83<br>Pan L K, Sun
- 1277-83
- 
- 
- 
- [4] Dey A, De S, De A and De S K 2004 Characterization and dielectric properties of polyaniline–TiO<sub>2</sub> nanocomposites *Nanotechnology* 15<br>
1277-83<br>
Fan L K, Sun C Q, Chen T P, Li S, Li C M and Tay B K 2004 Dielectric suppr Dey A, De S, De A and De S K 2004 Characterization and dielectric properties of polyaniline–TiO<sub>2</sub> nanocomposites *Nanotechnology* **15**<br>
Pan L K, Sun C Q, Chen T P, Li S, Li C M and Tay B K 2004 Dielectric suppression of n Family Results of Democration and Tay B K 2004 Dielectric suppression of nanosolid silicon *Nanotechnology* 15 1802-6<br>
Tanaka T 2005 Dielectric anocomposites with insulating properties *IEEE Transactions on Dielectrics and* Pan L K, Sun C Q, Chen T P, Li S, Li C M and Tay B K 2004 Dielectric suppression of nanosolid silice<br>Tanaka T 2005 Dielectric nanocomposites with insulating properties *IEEE Transactions on Dielectrics*<br>Wang T, Zhang B, Li Tanaka T 2005 Dielectric nanocomposites with insulating properties *IEEE Transactions on Dielectrics and Electrical Insulation* 12 914-28<br>
Vang T, Zhang B, Li D-Y, Hou Y-C and Zhang G-X 2020 Metal nanoparticle-doped epoxy
- 
- 
- Wang T, Zhang B, Li D-Y, Hou Y-C and Zhang G-X 2020 Metal nanoparticle-dop<br>insulators under DC voltage *Nanotechnology* 31<br>Wang T-Y, Zhang B-Y, Li D-Y, Hou Y-C and Zhang G-X 2020 A single-el<br>nanoparticle-doped epoxy resin ISI<br>
ISI Wang T-Y, Zhang B-Y, Li D-Y, Hou Y-C and Zhang G-X 2020 A single-electron tunneling model: a theoretical analysis of a metal<br>
nanoparticle-doped epoxy resin to suppress surface charge accumulation on insulators su Wang T-Y, Zhang B-Y, Li D-Y, Hou Y-C and Zhang G-X 2020 A single-electron tunneling model: a theoretical analysis of a metal<br>nanoparticle-doped epoxy resin to suppress surface charge accumulation on insulators subjected to Wang T-Y, Zhang B-Y, Li D-Y, Hou<br>nanoparticle-doped epoxy resin to suppres<br>Xue J, Chen J-H, Dong J-H, Deng J and<br>charge regulation using graded conductivi<br>Guan H, Chen X, Du H, Jiang T, Parama<br>plasma-treated silicone rubbe Kue J, Chen J-H, Dong J-H, Deng J and Zhang G-J 2020 Enhancing flashover performance of alumina/epoxy spacers by adaptive surface charge regulation using graded conductivity coating *Nanotechnology* 31 364002<br>
Guan H, Chen charge regulation using graded conductivity coating *Nanotechnology* 31 364002<br>
[10] Guan H, Chen X, Du H, Jiang T, Paramane A and Zhou H 2020 Surface potential decay and DC surface flashover characteristics of DBD<br>
plasma *Distribution Conference,* pp 484-8 vol.2<br> *Distribution Conference & Exposition (T&L*<br> *Distribution Conference & Exposition (T&L*<br> *Distribution Conference & Exposition (T&L*<br> *p* 1-5<br> *R.* Alvinsson, E. Borg, A. Hjortsb plasma-treated silicone rubber *Nanotechnology* **31** 424005<br>
[11] Riechert U, Straumann U and Gremaud R 2016 Compact gas-insulated systems for high voltage<br>
In: *IEEE PES Transmission & Distribution Conference & Exposition* 
	-
- 
- 
- Ricchert U, Straumann U and Gremaud R 2016 Compact gas-insulated systems for high voltage direct current transmission: Basic design.<br>
In: *IEEE PES Transmission & Distribution Conference & Exposition (T&D)*, (Kay Bailey Hu In: IEEE PES Transmission & Distribution Conference & Exposition (T&D), (Kay Bailey Hutchison Convention Center Dallas, Texas, USA<br>
Published By 2019 Surfaces Charging Theodore Converter Stations In: CIGRE<br>
Mendik M, Lowde **of Power and Energy Systems 6**<br> **of Power S M and Elliott F 1999 Long term**<br> *Distribution Conference*, pp 484-8 vol.2<br>
Li C *et al* 2020 J. Phys. D: Appl. Phys. https://doi.org/10.1<br>
Li C, Xu Y, Lin C, Chen G, Tu Y, Zhou Eta Munisson, E. Borg, A. Hjortsberg, T. Höglund and Hörnfeldt S 1986 GIS for HVDC Converter Stations. In: *CIGRE*<br>
Mendik M, Lowder S M and Elliott F 1999 Long term performance verification of high voltage DC GIS. In: *IE* Mendik M, Lowder S M and Elliott F 1999 Long term performance verificati<br>Distribution Conference, pp 484-8 vol.2<br>Li C et al 2020 J. Phys. D: Appl. Phys. https://doi.org/10.1088/1361-6463/abb38f<br>Li C, Xu Y, Lin C, Chen G, T
- 
- AUTHOR SUBMITTED MANUSCRIPT NANO-127285.R1 Page 50 of 54<br>
Li C, Hu J, Lin C and He J 2017 The potentially neglected culprit of DC surface flashover: electron migration under temperature gradients<br> *Scientific Reports* 7<br>
	- **AUTHOR SUBN**<br>*Li* C, Hu J, Lin C and He J 2017 The potentially<br>*Scientific Reports* 7<br>**An Z, Yin Q, Liu Y, Zheng F, Lei Q and Zhang**<br>Fluorination Temperature and Time *IEEE Transe* [18] An Z, Yin Q, Liu Y, Zheng F, Lei Q and Zhang Y 2015 Modulation of Surface Electrical Properties of Epoxy Resin Insulator by Changing
	- Fluit C, Hu J, Lin C and He J 2017 The potentially neglected culprit of DC surface flashover: electron migration under temperatur<br>Scientific Reports 7<br>An Z, Yin Q, Liu Y, Zheng F, Lei Q and Zhang Y 2015 Modulation of Surfa **Example 2018 AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1** Page 50 of 54<br>
	Li C, Hu J, Lin C and He J 2017 The potentially neglected culprit of DC surface flashover: electron migration under temperature gradients<br> *Scienti* AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br> *I.* C, Hu J, Lin C and He J 2017 The potentially neglected culprit of DC surface flashover: electron migra<br> *An Z*, Yin Q, Liu Y, Zheng F, Lei Q and Zhang Y 2015 Modulation of *I.i* C, Hu J, Lin C and He J 2017 The potentially neglected culprit of DC surface flashover: electron migration under temperatur<br>*ISEN ACE ACE 2017* The Distribution of Surface Electrical Properties of Epoxy Resin Insulat
	- Lin C, Hu J, Lin C and He J 2017 The potentially neglected culprit of DC surface flashover: electron migration under temperature gradients<br>
	Scientific Reports 7<br>
	An Z, Yin Q, Liu Y, Zheng F, Lei Q and Zhang Y 2015 Modulati Scientific Reports 7<br>
	18] An Z, Yin Q, Liu Y, Zheng F, Lei Q and Zhang Y 2015 Modulation of Surface Electrical Properties of Epoxy Resin Insulator by Changing<br>
	19 Fluorination Temperature and Time IEEE Transactions on Diel
- 
- An Z, Yin Q, Liu Y, Zheng F, Lei Q and Zhang Y 2015 Modulation of Surface Electrical Properties of Epoxy Resin Ins<br>Fluorination Temperature and Time *IEEE Transactions on Dielectrics and Electrical Insulation* **22** 226-34<br> Fluorination Temperature and Time *IEEE Transactions on Dielectrics and Electrical Insulation* **22 526-34**<br>
19 Liu Y, An Z, Cang J, Zhang Y and Zheng F 2012 Significant Suppression of Surface Charge Accumulation on Epoxy R *Physics* **113** Fluorination *IEEE Transactions on Dielectrics and Electrical Insulation* 19 1143-50<br>
(20) Liu Y, An Z, Cang J, Zheng F and Zhang Y 2011 Preliminary Study on Surface Properties of Surface Fluorinated Epoxy Resin Insulation
	-
- Liu Y, An Z, Cang J, Zheng F and Zhang Y 2011 Preliminary Study on Surface Properties of Surface Fluorinated E<br>
IEEE Proceedings of 2011 International Conference on Electrical Insulating Materials pp 109-12<br>
Liu Y, An Z, Y *IEEE Proceedings of 2011 International Conference on Electrical Insulating Materials pp 109-12*<br>
211 Liu Y, An Z, Yin Q, Zheng F, Lei Q and Zhang Y 2013 Characteristics and Electrical *Insulation* 20 1859-68<br>
221 Liu Y, A Liu Y, An Z, Yin Q, Zheng F, Lei Q and Zhang Y 2013 Characteristics and Electrical Properties<br>at Different Temperatures *IEEE Transactions on Dielectrics and Electrical Insulation* **20** 1859-68<br>Liu Y, An Z, Yin Q, Zheng F, The U.Y., An Z, Yin Q, Zheng F, Zhang Y and Lei Q 2013 Rapid potential decay on surface fluorinated epoxy resin samples *Journal of Applied*<br> *Physics* 113<br>
Que L, An Z, Ma Y, Shan F, Zhang Y, Zheng F and Zhang Y 2018 High Liu Y, An Z, Yin Q, Zheng F, Zhang Y and Lei Q 2013 Rapid potenti<br>*Physics* 113<br>Que L, An Z, Ma Y, Shan F, Zhang Y, Zheng F and Zhang Y 2018<br>Discharge in SF<sub>6</sub> Gas *IEEE Transactions on Dielectrics and Electrica*<br>Zhang B, *Physics* 113<br>
(23) Que L, An Z, Ma Y, Shan F, Zhang Y, Zheng F and Zhang Y 2018 High Resistance of Surface Fluorinated Epoxy Insulators to Surface<br>
Discharge in SF<sub>6</sub> Gas *IEEE Transactions on Dielectrics and Electrical I* Que L, An Z, Ma Y, Shan F, Zhang Y, Zheng F and Zhang Y 2018 High Resistance of Surf Discharge in SF<sub>6</sub> Gas *IEEE Transactions on Dielectrics and Electrical Insulation* **25** 245-52 Zhang B, Zhang G, Wang Q, Li C, Jinliang 1261 Discharge in SF<sub>6</sub> Gas *IEEE Transactions on Dielectrics and Electrical Insulation* 25 245-52<br>
23 Zhang B, Zhang G, Wang Q, Li C, Jinliang H and An Z 2015 Suppression of surface charge accumulation on Al<sub>2</sub>O<sub>3</sub>-filled *Chang B, Zhang G, Wang Q, Li C, Jinliang H and An Z 2015 Suppression of surface charge accumu insulator under DC voltage by direct fluorination <i>AIP Advances* 5 127207<br> *Mohamad A, Chen G, Zhang Y and An Z 2015 Surface Fl*
- 
- 
- insulator under DC voltage by direct fluorination *AIP Advances* 5 127207<br>
125] Mohamad A, Chen G, Zhang Y and An Z 2016 Moisture Effect on Surface Fluorinated Epoxy Resin for High-voltage DC Applications *on Dielectrics a*
- 
- Mohamad A, Chen G, Zhang Y and An Z 2015 Surface Fluorinated Epoxy Resin for High Voltage DC Application *IEEE Transact*<br>Dielectrics and Electrical Insulation 22 101-8<br>Mohamad A, Chen G, Zhang Y and An Z 2016 Moisture Effe Dielectrics and Electrical Insulation 22 101-8<br>
126] Mohamad A, Chen G, Zhang Y and An Z 2016 Moisture Effect on Surface Fluorinated Epoxy Resin for High-voltage DC Applications<br>
12916 Mohamad A, Chen G, Zhang Y and An Z 2 Mohamad A, Chen G, Zhang Y and An Z 2016 Moisture Effect on Surface Fluorinated Epoxy Resin for High-voltage DC *i*<br>*IEEE Transactions on Dielectrics and Electrical Insulation 23* 1148-55<br>Mohamad A, Chen G, Zhang Y and An *IEEE Transactions on Dielectrics and Electrical Insulation* 23 1148-55<br>
Mohamad A, Chen G, Zhang Y and An Z 2013 Influence of Fluorination Time on Surface Flashover of Polymeric Insulation. In: *IEEE*<br> *Conference on Elec Mohamad A, Chen G, Zhang Y and An Z 2013 Influence of Conference on Electrical Insulation and Dielectric Phenomena, Mohamad A, Chen G, Zhang Y and An Z 2013 Surface Potentia DC Applications. In: <i>IEEE Conference on Electr* For Conference on Electrical Insulation and Dielectric Phenomena, pp 482-5<br>
1323 Mohamad A, Chen G, Zhang Y and An Z 2013 Surface Potential Decay measurements on Fluorinated Polymeric Insulation for High Voltage<br>
DC Applic *Transactions on Dielectrics and Electrical Insulation and Dielectric Phenome Mohamad A, Chen G, Zhang Y and An Z 2014 Mechanisms for surface potential applications. In: <i>IEEE Conference on Electrical Insulation and Dielec* EXTED Mohamad A, Chen G, Zhang Y and An Z 2014 Mechanisms for surface potential decay on fluorinated epoxy in high voltage DC<br>
132) Mohamad A, Chen G, Zhang Y and An Z 2014 Mechanisms for surface potential decay on fluorin *Transactions A, Chen G, Zhang Y and An Z 2014 Mechanisms for surface potential applications. In: <i>IEEE Conference on Electrical Insulation and Dielectric Phenomena, pp* Du B, Du Q, Li J and Liang H 2018 Carrier mobility a
- -
	-
- applications. In: *IEEE Conference on Electrical Insulation and Dielectric Phenomena*, pp 863-6<br>
[30] Du B, Ru Z, Li J and Liang H 2018 Carrier mobility and trap distribution dependent flashover characteristics of epoxy re *Journal O. E.i J and Liang H 2018 Carrier mobility and trap distrib Transmission & Distribution 12 466-71*<br>*Du B, Ran Z, Li J and Liang H 2019 Novel Insulator with Intert Transactions on Dielectrics and Electrical Insulat* Transmission & Distribution 12 466-71<br>
[31] Du B, Ran Z, Li J and Liang H 2019 Novel Insulator with Interfacial sigma-FGM for DC Compact Gaseous Insulated Pipeline *IEEE*<br> *Transactions on Dielectrics and Electrical Insula* Du B, Ran Z, Li J and Liang H 2019 Novel Insulator with Interfacial *Transactions on Dielectrics and Electrical Insulation* 26 818-25 Li C, He J and Hu J 2016 Surface Morphology and Electrical Characteris *Transactions on* Transactions on Dielectrics and Electrical Insulation 26 818-25<br>
1321 Li C, He J and Hu J 2016 Surface Morphology and Electrical Characteristics of Direct Fluorinated Epoxy-resin/Alumina Composite *IEEE*<br> *Transactions on* Li C, He J and Hu J 2016 Surface Morphology and Electrical Characteristics Transactions on Dielectrics and Electrical Insulation 23 3071-77<br>Li C, Hu J, Lin C and He J 2016 The control mechanism of surface traps on<br>Journal Li C, Hu J, Lin C and He J 2016 The control mechanism of surface traps on surface charge behavior in *Journal of Physics D-Applied Physics* 49<br>Li C, Hu J, Lin C, Zhang B, Zhang G and He J 2016 Fluorine gas treatment improv
- 
- 
- Transactions on Dielectrics and Electrical Insulation 23 3071-77<br>
1331 Li C, Hu J, Lin C and He J 2016 The control mechanism of surface traps on surface charge behavior in alumina-filled epoxy composites<br> *Journal of Physi Journal of Physics D-Applied Physics* 49<br>
134] Li C, Hu J, Lin C, Zhang B, Zhang G and He J 2016 Fluorine gas treatment improves surface degradation inhibiting property of<br>
137 Li C, Hu J, Lin C, Zhang B, Zhang G and He J Li C, Hu J, Lin C, Zhang B, Zhang G and He J 2016 Fluorine gas treatment improves surface deg<br>alumina-filled epoxy composite Aip Advances 6<br>Li C, Hu J, Lin C, Zhang B, Zhang G and He J 2017 Surface charge migration and DC Examples alumina-filled epoxy composite Aip Advances 6<br>
136] Li C, Hu J, Lin C, Zhang B, Zhang G and He J 2017 Surface charge migration and DC surface flashover of surface-modified epoxy-based<br>
insulators Journal of Physic Li C, Hu J, Lin C, Zhang B, Zhang G and He J 2017 Surface charge migration and DC surface flashover of surface-modified epoxy-based<br>insulators *Journal of Physics D-Applied Physics* 50<br>Que L, An Z, Ma Y, Xie D, Zheng F and
- 
- 

- **Example 1991** Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge control on polymer surfaces by atmospheric-pressure plasma deposition *Journal of Applied Physics* 122 233302<br>[4 **AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1**<br>Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface chatmospheric-pressure plasma deposition *Journal of Applied Physics* **122** 233302<br>Zhan **EXECUTE AT ANNO-127285.R1**<br>
Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge control on polymer surfaces by<br>
atmospheric-pressure plasma deposition *Journal of Applied Physics*
- 
- **AUTHOR SUBMITTED MANUSCRIPT NANO-127285.R1**<br>
Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge control on polymer surfa<br>
atmospheric-pressure plasma deposition *Journal of Ap* **EXECT THE SUBMITTED MANUSCRIPT - NANO-127285.R1**<br>
Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge control on polymer surfaces by<br>
atmospheric-pressure plasma deposition *Jour* AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge contr<br>
atmospheric-pressure plasma deposition *Journal of Applied Physics* 122 23 Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge control on polymer surfaces by<br>atmospheric-pressure plasma deposition *Journal of Applied Physics* 122 233302<br>(40) Zhang C, Li Wang R, Lin H, Gao Y, Ren C, Ostrikov K and Shao T 2017 Inorganic nanofilms for surface charge control on pot atmospheric-pressure plasma deposition *Journal of Applied Physics* 122 233302<br>
Zhang C, Lin H, Zhang S, Xie Q, atmospheric-pressure plasma deposition *Journal of Applied Physics* 122 233302<br>
(40) Zhang C, Lin H, Zhang S, Xie Q, Ren C and Shao T 2017 Plasma surface treatment to improve surface charge accumulation of epoxy resin expo Zhang C, Lin H, Zhang S, Xie Q, Ren C and Shao T 2017 Plasma surface treatment to improve sof epoxy resin exposed to DC and nanosecond-pulse voltages *Journal of Physics D-Applied Physics* Zhang C, Ma Y, Kong F, Wang R, Re of epoxy resin exposed to DC and nanosecond-pulse voltages *Journal of Physics D-Applied Physics* 50 405203<br>
The Zhang C, Ma Y, Kong F, Wang R, Ren C and Shao T 2019 Surface Charge Decay of Epoxy Resin Treated by AP-DBD De *2018 12th International Conference on the Properties and Applications of Dielectrics Material Conference Design Internation Internation and Direct Fluorination <i>IEEE Transactions on Dielectrics and Electrical Insulation*
- Direct Fluorination *IEEE Transactions on Dielectrics and Electrical Insulation* 26 768-75<br>
2hang C, Ma Y, Kong F, Yan P, Chang C and Shao T 2019 Atmospheric pressure plasmas and direct fluorination treatment of Al<sub>2</sub>O<sub>3</sub> Zhang C, Ma Y, Kong F, Yan P, Chang C and Shao T 2019 Atmospheric pressure plasmas and direct fluorination treatment of Al<sub>2</sub>O<sub>3</sub>-fill<br>epoxy resin: A comparison of surface charge dissipation *Surface & Coatings Technology*
- 
- Hai B, Zhang C, Wang R, Zhang S, Chen G and Shao T 2017 Plasma-deposited SiO<sub>2</sub>-like thin film suppresses charge accepoxy resin surface *High voltage technology* 43 375-84 (in Chinese)<br>
Yue W, Min D, Nie Y and Li S 2018 Pl
- 
- epoxy resin: A comparison of surface charge dissipation *Surface & Coatings Technology* 362 1-11<br>
1461 Hai B, Zhang C, Wang R, Zhang S, Chen G and Shao T 2017 Plasma-deposited SiO<sub>2</sub>-like thin film suppresses charge accumu epoxy resin surface *High voltage technology* 43 375-84 (in Chinese)<br>
Tu W, Min D, Nie Y and Li S 2018 Plasma treatment enhances surface flashover performance of EP/Al<sub>2</sub>O<sub>2</sub>micro-composite in vacuum. In:<br>
2018 12th Intern The W, Min D, Nie Y and Li S 2018 Plasma treatment enhances surface flashover performance of EP/Al<sub>2</sub>O<sub>3</sub>micro-composite in vacuum. In: *IO18 12th International Conference on the Properties and Applications of Dielectric M* 2018 12th International Conference on the Properties and Applications of Dielectric Materials (ICPADM), pp 1086-9<br>
Tu Y, Zhou F, Cheng Y, Jiang H, Wang C, Bai F and Lin J 2018 The Control Mechanism of Micron and Nano SiO<sub></sub> *the 2010 IEEE International Conference on Solid Dielectrics* Coating on Surface Charge in Epoxy Resin *IEEE Transactions on Dielectrics and Electrical Insulation* 25 1275-84<br>
Tu Y, Zhou F, Jiang H, Bai F, Wang C, Lin J and Cheng Y 2018 Effect of Nano-TiO<sub>2</sub>/EP Composite Coating on D Tu Y, Zhou F, Jiang H, Bai F, Wang C, Lin J and Cheng Y 2018 Effect of Nano-TiO<sub>2</sub>/EP Composite Coating on Dy<br>Surface Charge in Epoxy Resin *IEEE Transactions on Dielectrics and Electrical Insulation* 25 1308-17<br>Gao Y, Du
- -
	-
- Surface Charge in Epoxy Resin *IEEE Transactions on Dielectrics and Electrical Insulation* 25 1308-17<br>
Gao Y, Du B , Cui J and Wu K 2011 Effect of Gamma-Ray Irradiation on Lateral Charge Motion on Surface of Laminated Poly
- Gao Y, Du B, Cui J and Wu K 2011 Effect of Gamma-Ray Irradiation on Lateral Charge<br>Insulating Materials. In: *IEEE Annual Report Conference on Electrical Insulation and Dielectric*<br>Gao Y, Du B, Ma Z and Zhu X 2010 Decay Be Insulating Materials. In: *IEEE Annual Report Conference on Electrical Insulation and Dielectric Phenomena, Vols 1 And 2, pp 153-6*<br>
(48) Gao Y, Du B, Ma Z and Zhu X 2010 Decay Behavior of Surface Charge on Gamma-Ray Irrad Gao Y, Du B, Ma Z and Zhu X 2010 Decay Behavior of Surface Charge on Gamma-Ray Irradiated Epothe 2010 IEEE International Conference on Solid Dielectrics<br>
Huang Y, Min D, Xie D, Li S, Wang X and Lin S 2017 Surface Flashover *the 2010 IEEE International Conference on Solid Dielectrics*<br>
[49] Huang Y, Min D, Xie D, Li S, Wang X and Lin S 2017 Surface Flashover Performance of Epoxy Resin Microcomposites Infulenced by<br>
Dzone Treatment. In: 2017 I Huang Y, Min D, Xie D, Li S, Wang X and Lin S 2017 Surface Flashover Performance of Epoxy Resi<br>Ozone Treatment. In: 2017 *International Symposium on Electrical Insulating Materials*<br>Baytekin H T, Baytekin B, Hermans T M, K Coone Treatment. In: 2017 International Symposium on Electrical Insulating Materials<br>
[50] Baytekin H T, Baytekin B, Hermans T M, Kowalczyk B and Grzybowski B A 2013 Control of Surface Charges by Radicals as a Principle o Baytekin H T, Baytekin B, Hermans T M, Kowalczyk B and Grzybowski B A 2013 Cor<br>Antistatic Polymers Protecting Electronic Circuitry *Science* **341** 1368-71<br>Li C, Hu J, Lin C and He J 2016 Hot Electron Injection Regulation i Antistatic Polymers Protecting Electronic Circuitry Science 341 1368-71<br>
154 C., Hu J, Lin C and He J 2016 Hot Electron Injection Regulation in Al<sub>2</sub>O<sub>J</sub>-filled Epoxy Resin Composite Using Cr<sub>2</sub>O<sub>J</sub> Coatings. In:*IEEE*<br> *C* Li C, Hu J, Lin C and He J 2016 Hot Electron Injection Regulation in Al<sub>2</sub>O<sub>3</sub>-filled Epoxy Resin Composite Using Cr<sub>2</sub>O<sub>3</sub> Coatings. In:*IEEE*<br>Conference on Electrical Insulation and Dielectric Phenomena, pp 101-4<br>Zhang B
- Conference on Electrical Insulation and Dielectric Phenomena, pp 101-4<br>
[52] Zhang B, Gao W, Hou Y and Zhang G 2018 Surface Charge Accumulation and Suppression on Fullerene-filled Epoxy-resin Insulator under<br>
DC Voltage *I* 
	- He S, Lin C, Hu J, Li C and He J 2018 Tailoring charge transport in epo<br>asbestine whiskers *Journal of Physics D-Applied Physics* 51<br>Ootera H and Nakanishi K 1988 Analytical method for evaluating s<br>measurement-application
	- Ootera H and Nakanishi K 1988 Analytical meth<br>
	measurement-application to a cone-type spacer in +c<br>
	Nitta T and Nakanishi K 1991 Charge accumulatio<br>
	418-27<br>
	Fujinami H, Takuma T, Yashima M and Kawamo<br>
	Spacers *IEEE Power E*
	- 418-27 DC Voltage IEEE Transactions on Dielectrics and Electrical Insulation 25 2011-9<br>
	1668, Lin C, Hu J, Li C and He J 2018 Tailoring charge transport in epoxy based composite under temperature gradient using K<sub>2</sub>Ti<sub>8</sub>O<sub>13</sub> and asbestine whiskers *Journal of Physics D-Applied Physics* 51<br>
	[54] Ootera H and Nakanishi K 1988 Analytical method for evaluating surface charge distribution on a dielectric from capacitive probe<br>
	measurement-application t **Transactions on Power Apparatus and Systems PAS-102** 3919-27<br> **Pujinami H, Takuma T, Yashima M and Kawamoto T 1989 Mechanism and Effect of**<br> **Spacers IEEE Power Engineering Review 9 62-**<br> **Cooke C M and Trump J G 1973 Pos**
	- Fujinami H, Takuma T, Yashima M and Kawamoto T 1989 Mechanism and Effect of DC Charge Accumulat Spacers *IEEE Power Engineering Review* 9 62-<br>Cooke C M and Trump J G 1973 Post-Type Support Spacers for Compressed Gas-Insula
	- *Transactions on Dielectrics and Electrical Insulation* 11 949-63<br> *Transactions on Power Apparatus and Systems PAS-102 3919-27*<br> *Transactions on Power Apparatus and Systems PAS-102 3919-27*<br> *Transactions on Power Appara*
	- measurement-application to a cone-type spacer in +or-500 kV DC-GIS *IEEE Transactions on Power Delivery* 3 165-72<br>
	Nitta T and Nakanishi K 1991 Charge accumulation on insulating spacers for HVDC GIS *IEEE Transactions on E* 186]<br>
	Fujinami H, Takuma T, Yashima M and Kawamoto T 1989 Mechanism and Effect of DC Charge Accumulation on SF<sub>6</sub> Gas Insulated<br>
	Spacers *IEEE Power Engineering Review* 9 62-<br>
	Cooke C M and Trump J G 1973 Post-Type Support Spacers *IEEE Power Engineering Review* 9 62-<br>
	[57] Cooke C M and Trump J G 1973 Post-Type Support Spacers for Compressed Gas-Insulated Cables *IEEE Transactions on Power Apparatus*<br>
	and Systems **PAS-92** 1441-7<br>
	Nakanishi
	-
	-

- AUTHOR SUBMITTED MANUSCRIPT NANO-127285.R1<br>
Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and Cheng Y 2019 100-kV HVDC SF<sub>6</sub>/N<sub>2</sub> Gas-Insulated Transmission Line *IEEE*<br> *Transactions on Power Delivery* 1-<br>
Jia Z, Zhang **AUTHOR SUBMITTED MAN**<br>*Tu Y*, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and C<br>*Transactions on Power Delivery* 1-<br>Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2009 Flashov<br>1903-7 (in Chinese) For The Control of SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and Cheng Y 2019 100-kV HVDC SF<sub>6</sub>/N<sub>2</sub> Gas-Insulated Transmission Line *IEEE*<br>
Transactions on Power Delivery 1-<br>
Ji
	-
- AUTHOR SUBMI<br>
Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H,<br> *Transactions on Power Delivery* 1-<br>
Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2<br>
1903-7 (in Chinese)<br>
Liang H, Du B, Li J, Li Z and Li A 2018 Effect<br>
composites **Example 19 AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1** Page 52 of 54<br>
Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and Cheng Y 2019 100-kV HVDC SF<sub>6</sub>/N<sub>2</sub> Gas-Insulated Transmission Line *IEEE*<br> *Transactions on Power* AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and Cheng Y 2019 100-kV HVDC SF<sub>6</sub>/N<sub>2</sub> *C*<br>*Transactions on Power Delivery* 1-<br>Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2009 Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and Cheng Y 2019 100-kV HVDC SF<sub>6</sub>/N<sub>2</sub> Gas-Insulated Transmission Line *IEEE*<br> *Fransactions on Power Delivery* 1-<br>
Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2009 Flashov Tu Y, Chen G, Li C, Wang C, Ma G, Zhou H, Ai X and Cheng Y 2(*Transactions on Power Delivery* 1-<br>*Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2009 Flashover charact*<br>1903-7 (in Chinese)<br>Liang H, Du B, Li J, Li Z and Li A Transactions on Power Delivery 1-<br>
162] Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2009 Flashover characteristics of insulators in SF<sub>8</sub> under DC *High voltage technology* 35<br>
1903-7 (in Chinese)<br>
1619 Liang H, Du B, Li Jia Z, Zhang Q, Zhang B, Fan J, Li J and Li P 2009 Flashover characteristics of insulators in SF<sub>6</sub> un 1903-7 (in Chinese)<br>Liang H, Du B, Li J, Li Z and Li A 2018 Effects of non-linear conductivity on charge trapping and d 1903-7 (in Chinese)<br>
1663 Liang H, Du B, Li J, Li Z and Li A 2018 Effects of non-linear conductivity on charge trapping and de-trapping behaviours in epoxy/SiC<br>
1664 Composites under DC stress *IET Science, Measurement & T* Liang H, Du B, Li J, Li Z and Li A 2018 Effects of non-linear conductivity on charge trapping and de-trapping beh<br>composites under DC stress *IET Science, Measurement & Technology* **12** 83-9<br>Li J, Liang H, Du B and Wang Z
- 
- *Di* J, Liang H, Du B and Wang Z 2019 Surface Functional Graded Sp on Dielectrics and Electrical Insulation 26 664-7<br>
Du B, Liang H, Li J and Zhang C 2018 Temperature dependent composites *IEEE Transactions on Dielectrics*
- composites under DC stress *IET Science, Measurement & Technology* 12 83-9<br>
[64] Li J, Liang H, Du B and Wang Z 2019 Surface Functional Graded Spacer for Compact HVDC Gaseous Insulated System *IEEE Transactions*<br>
on *Diele* on Dielectrics and Electrical Insulation 26 664-7<br>
Du B, Liang H, Li J and Zhang C 2018 Temperature dependent surface potential decay and flashover characteristics of epoxy/SiC<br>
composites IEEE Transactions on Dielectrics Du B, Liang H, Li J and Zhang C 2018 Temperature dependent surface potential decay and flashover characteristics of epoxy/SiC composites *IEEE Transactions on Dielectrics and Electrical Insulation* 25 631-8<br>He S, Li C, Lin composites *IEEE Transactions on Dielectrics and Electrical Insulation* 25 631-8<br>
166] He S, Li C, Lin C, Hu J, He J and Sun Z 2019 Feasibility analysis and verification of potential application of nonlinear materials in c He S, Li C, Lin C, Hu J, He J and Sun Z 2019 Feasibility analysis and verification of potential application of nonlinear materials in c<br>control of gas-solid interface *Journal of Power System and Automation* 1-7 (in Chines
	-
- control of gas-solid interface *Journal of Power System and Automation* 1-7 (in Chinese)<br>
[67] Du B, Liang H and Li J 2019 Interfacial E-Field Self-Regulating Insulator Considered for DC GIL Application *IEEE Transactions* Xue J, Chen J, Dong J, Sun G, Deng J and Zhang G-J 2020 A novel sight for understanding surface charging phen<br>HVDC GIL spacers with non-uniform conductivity *International Journal of Electrical Power* & *Energy Systems* 12
- 
- 
- Du B, Liang H and Li J 2019 Interfacial E-Field Self-Regulating Insulator Considered for DC GIL Application *IEEE Transactions on*<br>Dielectrics and Electrical Insulation 26 801-9<br>Xue J, Chen J, Dong J, Sun G, Deng J and Zha Dielectrics and Electrical Insulation 26 801-9<br>
[68] Xue J, Chen J, Dong J, Sun G, Deng J and Zhang G-J 2020 A novel sight for understanding surface charging phenomena on downsized<br>
HVDC GIL spacers with non-uniform conduc HVDC GIL spacers with non-uniform conductivity *International Journal of Electrical Power* & *Energy Systems* 120 105979<br>
Xue J, Chen J, Dong J, Wang H, Li W, Deng J and Zhang G 2019 The regulation mechanism of SiC/epoxy c
- 
- Xue J, Chen J, Dong J, Wang H, Li W, Deng J and Zhang G 2019 The regulation mechanism of SiC/epoxy coatings on surface charge behavior and flashover performance of epoxy/alumina spacers *Journal of Physics D-Applied Physic* behavior and flashover performance of epoxy/alumina spacers *Journal of Physics D-Applied Physics* 52 405502<br>
To The U. Li V, Dong J, Chen J, Li W, Deng J and Zhang G 2020 Surface charge transport behavior and flashover me Xue J, Li Y, Dong J, Chen J, Li W, Deng J and Zhang G 2020 Surface charge transport behavior and flashove<br>alumina/epoxy spacers coated by SiC/epoxy composites with varied SiC particle size *Journal of Physics D Applied Phy* alumina/epoxy spacers coated by SiC/epoxy composites with varied SiC particle size Journal of Physics D Applied Physics 53 155503<br>
Pan Z, Tang J, Pan C, Luo Y, Liu Q and He H 2020 Contribution of Nano-SiC/Epoxy Coating wit
- 
- Pan Z, Tang J, Pan C, Luo Y, Liu Q and He H 2020 Contribution of Nano-SiC/Epoxy Coating with Nonlinear Conduction Charsurface Charge Accumulation under DC Voltage *Journal of Physics D: Applied Physics*<br>Li C, Lin C, Hu J, Surface Charge Accumulation under DC Voltage *Journal of Physics* D: *Applied Physics*<br>
172] Li C, Lin C, Hu J, Liu W, Li Q, Zhang B, He S, Yang Y, Liu F and He J 2018 Novel HVDC Spacers by Adaptively Controlling Surface<br> Li C, Lin C, Hu J, Liu W, Li Q, Zhang B, He S, Yang Y, Liu F and He J 2018 Novel HVDC Spacers by Adaptively Controlling Surface Charges - Part I: Charge Transport and Control Strategy *IEEE Transactions on Dielectrics and* Li C, Lin C, Hu J, Liu W, Li Q, Zhang B, He S, Yang Y, Liu Charges – Part I: Charge Transport and Control Strategy *IEEE* 1<br>*Li* C, Lin C, Yang Y, Zhang B, Liu W, Li Q, Hu J, He S, Li<br>charges – part ii: experiment *IEEE Tr* charges – part ii: experiment *IEEE Transactions on Dielectrics and Electrical Is* Li C, Lin C, Zhang B, Liu W, Yang Y, Liu F, Liu X, Hu J and He J 2018 Nov part iii: industrialization prospects *IEEE Transactions on Diele* **IVENTATA INTERT INTERT:** Industrialization prospects *IEEE Transactions on Dielectrics and Electrical Insulation* **25** 1259-66 Li C, Liu B, Wang J, Gong R, Wang G, Lei Z, Fabiani D, Lin C and Hu J 2019 Novel HVDC Spacers
- [75] Li C, Lin C, Yang Y, Zhang B, Liu W, Li Q, Hu J, He S, Liu X and He J 2018 Novel HVDC spacers by adaptively controlling surface charges part ii: experiment *IEEE Transactions on Dielectrics and Electrical Insulatio* Li C, Lin C, Yang Y, Zhang B, Liu W, Li Q, Hu J, He S, Liu X and He J 2018 Novel HVDC spacers by adaptively controlling surface charges – part ii: experiment *IEEE Transactions on Dielectrics and Electrical Insulation* 25 [74] Li C, Lin C, Zhang B, Liu W, Yang Y, Liu F, Liu X, Hu J and He J 2018 Novel HVDC spacers by adaptively controlling surface charges—<br>part iii: industrialization prospects *IEEE Transactions on Dielectrics and Electrica* [75] Li C, Liu B, Wang J, Gong R, Wang G, Lei Z, Fabiani D, Lin C and Hu J 2019 Novel HVDC Spacers in GIS/GIL by Adaptively Controlling Surface Charges - Insulation Compounding Scheme. In: 2019 2nd International Conferenc Surface Charges - Insulation Compounding Scheme. In: 2019 2nd International Conference on High Voltage Eng.<br>
Systems (ICHVEPS), pp 268-71<br>
Götz T, Kosse M, Riechert U, Abbasi A, Castellon J, Cavallini A, Esterl F, Geissler (76) Götz T, Kosse M, Ricchert U, Abbasi A, Castellon J, Cavallini A, Esterl F, Geissler M, Hochbrückner B, Kharezy M, Küchler A, N<br>
S, Neuhold S, Pietsch R, Pirker A, Plath R, Reuter M, Rossner M and Seltzer-Grant M 2019 S, Neuhold S, Pietsch R, Pirker A, Plath R, Reuter M, Rossner M and Seltzer-Grant M 2019 Progress on Partial discharge detection under<br>DC voltage stress *Interim Report of WG D1.*63<br>
Zhang G, Wang X, Yan Z, Liu Y, Okada M,
	-
	- *Herory of WG D1.*<br> *Herory of WG D1.*<br> *Herory Cyclang G, Wang X, Yan Z, Liu Y, Okada MEEE Transactions on Dielectrics and Electr*<br> *Griseri V, Dissado L A, Fothergill J, Teyssedivergent and uniform field IEEE Transactic* 271 The Transactions on Dielectrics and Electrical Insulation 9 187-93 doi: 10.1109/94.993734.<br>
	28 The Transactions on Dielectrics and Electrical Insulation 9 187-93 doi: 10.1109/94.993734.<br>
	28 Griseri V, Dissado L. A, Fot IEEE Transactions on Dielectrics and Electrical Insulation 9 187-93 doi: 10.1109/94.993734.<br>
	Griseri V, Dissado L A, Fothergill J, Teyssedre G and Laurent C 2002 Electroluminescence excitation mechanisms in an epoxy resin Griseri V, Dissado L A, Fothergill J, Teyssedre G and Laurent C 2002 Electroluminescence excitation mechanisms in an epoxy resin under<br>divergent and uniform field *IEEE Transactions on Dielectrics and Electrical Insulation*
	-
	- *III IEEE Transactions on Dielectrics and Electrical Insulation* **2** 150 Lin *C et al* Luminescence reveals micro discharge triggered surface flashover *submitted to J* Shao T, Wang R, Zhang C, Yan P 2018 Atmospheric-pre
	-
	-

- **AUTHOR SUBMITTED MANUSCRIPT NANO-127285.R1**<br>
(83) Zhang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar structure as a superior<br>
charge dissipation coating on insulators f
- AUTHOR SUBMITTED MANUSCRIPT NANO-127285.R1<br>Zhang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar stricharge dissipation coating on insulators for HVDC gas-insulated systems **EXECUTE AN AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1**<br>
IRAD 2012 A self-assembled, nacre-mimetic, nano-laminar structure as a superior<br>
charge dissipation coating on insulators for HVDC gas-insulated systems *Nanoscale* AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
Zhang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar structure as a superior<br>
charge dissipation coating on insulators for HVDC **AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1**<br>
Thang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar structure as a superior<br>
charge dissipation coating on insulators for HV
- 
- AUTHOR SUBMITTED MANUSCRIPT NANO-127285.R1<br>
Zhang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar structure as a superior<br>
charge dissipation coating on insulators for HVDC Thang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar structure as a superior<br>charge dissipation coating on insulators for HVDC gas-insulated systems *Nanoscale* 11 18046-51
- Zhang B, Wang Q, Zhang Y, Gao W, Hou Y and Zhang G 2019 A self-assembled, nacre-mimetic, nano-laminar structure<br>charge dissipation coating on insulators for HVDC gas-insulated systems *Nanoscale* 11 18046-51<br>Iwabuchi H, Do The United States of the Hanna R, Manual A, Hidaka K, Hoshina Y and Takei M 2012 Influence of Surface-Conductivity Nonuniformity<br>
187] Invabuchi H, Donen T, Matsuoka S, Kumada A, Hidaka K, Hoshina Y and Takei M 2012 Influ *Ivaluechi H, Donen T, Matsuoka S, Kumada A, Hidaka K, Hoshina Y and Takei M 2012 Infl on Charge Accumulation of GIS Downsized Model Spacer under DC Field Application <i>Electric Xue J, Wang H, Chen J, Li K, Liu Y, Song B, D* on Charge Accumulation of GIS Downsized Model Spacer under DC Field Application *Electrical Engineering In Japan* 181 29-36<br>
Xue J, Wang H, Chen J, Li K, Liu Y, Song B, Deng J and Zhang G 2018 Effects of surface roughness The J, Wang H, Chen J, Li K, Liu Y, Song B, Deng J and Zhang G 2018 Effects of surface ro<br>characteristics and surface flashover performance of alumina-filled epoxy resin spacers *Journal of A*<br>Chu P, Zhang H, Zhao J, Gao F characteristics and surface flashover performance of alumina-filled epoxy resin spacers *Journal of Applied Physics* 124<br>
[86] Chu P, Zhang H, Zhao J, Gao F, Guo Y, Dang B and Zhang Z 2017 On the volume resistivity of sili
- -
- Chu P, Zhang H, Zhao J, Gao F, Guo Y, Dang B and Zhang Z 2017 On the volume redifferent surface modifications *Composites Part a-Applied Science And Manufacturing* 99<br>Hanna R, Lesaint O, and Zavattoni L 2016 Dark Current M different surface modifications *Composites Part* a-*Applied Science And Manufacturing* 99 139-48<br>
[87] Hanna R, Lesaint O, and Zavattoni L 2016 Dark Current Measurements in Humid SF<sub>6</sub> at High Uniform Electric Field. In: *1999 Electrical Insulation and Dielectric Phenomena, pp 19-22*<br> *2016 Dark Current Measurements in Humid SF<sub>6</sub> at High Uniform Electric Field*<br> *2016 Dark Current Measurements in Humid SF<sub>6</sub>: influence of relative humidit International I., Hanna R, Lesaint O and Gallot-Lavallee O 2015 Dark current measurements in humid SF<sub>6</sub>: influence relative humidity and pressure <i>Journal of Physics D-Applied Physics* 48<br> *Internationi L, Lesaint O and* Zavattoni L, Lesaint O and Gallot-Lavallee O 2013 Dark Current Measurements in Pressurize<br>Electrical Insulation and Dielectric Phenomena, pp 659-62<br>Messerer F and Boeck W 1999 High resistance surface coating of solid insul Messerer F and Boeck W 1999 High resistance surface coating of solid insulating components for HVDC metal enclos 1999 Eleventh International Symposium on High Voltage Engineering, pp 63-6 vol.4<br>Messerer F, Finkel M and Boe
- For *Characterical Insulation and Dielectric Phenomena*, pp 19-22<br>
1913 Cavattoni L, Hanna R, Lesaint O and Gallot-Lavallee O 2015 Dark current measurements in humid SF<sub>6</sub>: influence of electrode roughness,<br>
relative humid relative humidity and pressure *Journal of Physics D-Applied Physics* 48<br>
[89] Zavattoni L<sub>3</sub> Lessint O and Gallot-Lavallee O 2013 Dark Current Measurements in Pressurized Air, N<sub>2</sub>, and SF<sub>6</sub>. In: *IEEE Conference on*<br> *E* Electrical Insulation and Dielectric Phenomena, pp 659-62<br>
[90] Messerer F and Boeck W 1999 High resistance surface coating of solid insulating components for HVDC metal enclosed equipment. In:<br>
1999 Eleventh International 1999 Eleventh International Symposium on High Voltage Engineering, pp 63-6 vol.4<br>
1911 Messerer F, Finkel M and Boeck W 2002 Surface charge accumulation on HVDC-GIS-spacer. In: *Conference Record of the the 2002 IEEE*<br> *I* Messerer F, Finkel M and Boeck W 2002 Surface charge accumulation on HVDC-GIS-spacer. In: *Conference Record of the th*<br> *International Symposium on Electrical Insulation (Cat. No.02CH37316), pp 421-5*<br>
Winter A, Kindersbe
- 
- 
- *International Symposium on Electrical Insulation (Cat. No.02CH37316),* pp 421-5<br>
Winter A, Kindersberger J, Tenzer M, Hinrichsen V, Zavattoni L, Lesaint O, Muhr M and Imamovic D 2015 Solid/Gaseous Insulation<br>
Systems for
- 
- *Winter A, Kindersberger J, Tenzer M, Hinrichsen V, Zavattoni L, Lesaint O, Muhr M and Imamovic D 20* Systems for Compact HVDC Solutions *Cigre Science & Engineering* **1**<br>*Winter A, Kindersberger J, Hinrichsen V, Imamovic* Systems for Compact HVDC Solutions *Cigre Science & Engineering* 1<br>
[93] Winter A, Kindersberger J, Hinrichsen V, Imamovic D and Tenzer M 2013 Compact Gas-Solid Insulating Systems for High-Field-Stress in<br>
HVDC application Winter A, Kindersberger J, Hinrichsen V, Imamovic D and Tenzer M 2013 Compact Gas-Solid Insulating Systems for High-Field-Stress in<br>HVDC applications In: *CIGRE Study Committee B3 & Study Committee D1 Colloquium*<br>Zhang B a Winter A, Kindersberger J, Hinrichsen V, Ima<br> *HVDC* applications In: *CIGRE Study Committe*<br> *Zhang B and Zhang G 2018 A Summary of the*<br> *Regulation and Suppression Strategies Journal*<br> *Mangelsdorf C W and Cooke C M 197* The School of Maximum of the Research on the Charge Characteristics of the Solid-Gas Interface in DC GIL II: Charge Regulation and Suppression Strategies *Journal of Electrical Engineering* 33 5145-58 (in Chinese)<br>
Mangels Zhang B and Zhang G 2018 A Summary of the Research on the Charge Characteristics of the Solid-Gas Interface in DC GIL II: Charge Regulation and Suppression Strategies *Journal of Electrical Engineering* 33 5145-58 (in Chin *Regulation and Suppression Strategies Journal of Electrical Engineering*<br> *Mangelsdorf C W and Cooke C M 1978 Static charge accumulated by e<br>
<i>Electrical Insulation & Dielectric Phenomena - Annual Report 1978, pp*<br> *CIGRÉ* Mangelsdorf C W and Cooke C M 1978 Static charge accumulated by epoxy post insulation stressed at high DC voltages. In: *Conference on*<br> *Electrical Insulation & Dielectric Phenomena - Amual Report 1978*, pp 220-7<br>
CIGRÉ *IEER Insulation & Dielectric Phenomena - Annual Report 1978*, pp 220-7<br> *CIGRÉ Working Group D1.03 (TF11) E, F., Giboulet A, Girodet A, Hama H, Hanai M, Juhre* H-G, Meijer S, Neumann C, S. O, Riechert U and Schichler U [96] CIGRÉ Working Group D1.03 (TF11) E, F., Giboulet A, Girodet A, Hama H, Hanai M, Juhre K, Kindersberger J, Koltunowicz W, Kranz H-G, Melier S, Neumann C, S. O, Ricehert U and Schichler U 2012 Gas Insulated Systems for
- 
- 
- H-G, Meijer S, Neumann C, S. O, Riechert U and Schichler U 2012 Gas Insulated Systems for HVDC: DC Stress at DC and AC Systems<br> *CIGRÉ Brochure*<br>
Riechert U, Hama H, Endo F, Juhre K, Kindersberger J, Meijer S, Neumann C, O *CIGRÉ Brochure*<br> *Riechert U, Hama H, Endo F, Juhre K, Kindersberger J, Meijer S, Neumann C, Okal*<br> *Prick D1.03.11.* 2010 Gas Insulated Systems for HVDC. In: 2010 *ETG*<br> *Mischfeldbeanspruchung,* (Köln, Germany<br> *Strauma* Mischfeldbeanspruchung, (Köln, Germany<br>
Straumann U, Schueller M and Franck C 2012 Theoretical Investigation of HVDC Disc Spacer Charging in SF<sub>6</sub> Gas Insulated S:<br> *CIEEE Transactions on Dielectrics and Electrical Insulat* Gremaud R, Molitor F, Doiron C, Krivda A, C<br>in DC gas insulated systems. In: 4. ETG<br>Prüfverfahren, Lebensdauer 12.-13., (Dresden,<br>Gremaud R, Doiron C, Baur M, Simka P,<br>Straumann U 2016 Solid-gas insulation in HV<br>operation.
- [97] Riechert U, Hama H, Endo F, Juhre K, Kindersberger J, Meijer S, Neumann C, Okabe S and Schichler U On behalf of CIGRÉ Task Force<br>
D.03.11. 2010 Gas Insulated Systems for HVDC. In: 2010 ETG Fachtagung: Isoliersysteme b 1910. Straumann U, Schueller M and Franck C 2012 Theoretical Investigation of HVDC Disc Spacer Charging in SF<sub>6</sub> Gas Insulated Systems<br>
Straumann U, Schueller M and Franck C 2012 Theoretical Investigation of HVDC Disc Spac [108] Straumann U, Schueller M and Franck C 2012 Theoretical Investigation of HVDC Disc Spacer Charging in SF<sub>6</sub> Gas Insulated Systems<br> *IEEE Transactions on Dielectrics and Electrical Insulation* 19 2196-205<br>
(Gremaud R, *IEEE Transactions on Dielectrics and Electrical Insulation* 19 2196-205<br> *Cremaud R, Molitor F, Doiron C, Krivda A, Christen T, Johansson K, Lavesson N, Riechert U and Straumann U 2013 Solid-gas interfaces<br>
in DC gas insu*
- 
- in DC gas insulated systems. In: 4. *ETG-Fachtagung Grentflächen in elektrischen Isoliersystemen: Beanspruchungen, Design, Prüfverfahren, Lebensdauer 12.-13., (Dresden, Germany UI00)<br>
Gremaud R, Doiron C, Baur M, Simka P, Prüfverfahren, Lebensdauer 12.-13.*, (Dresden, Germany<br>
Gremaud R, Doiron C, Baur M, Simka P, Teppati V, Kallstrand B, Johansson K, Kosse M, Speck J, Großmann S, Riechert U and<br>
Straumann U 2016 Solid-gas insulation in HV Gremaud R, Doiron C, Baur M, Simka P, Teppati V, Kallstran<br>Straumann U 2016 Solid-gas insulation in HVDC gas-insulated sys<br>operation. In: *CIGRÉ Report D1-101*, 46th *CIGRÉ Session*, (Palais de<br>Riechert U, Straumann U and

- Fig. 2007 Salthouse E C and McIlhagger D S 1962 The measurement of surface resistivity. In: *Proceedings of the IEE Part A: Power Engineering,*<br>
pp 41-4<br>
2007 Influence of Trap Parameters of Composite Materials on Its Fl AUTHOR <br>
Salthouse E C and McIlhagger D S 1962<br>
pp 41-4<br>
Zhao W, Zhang G and Yan Z 2007 Infl<br>
Voltage Pulses in Vacuum Chinese Societ Figure 2012 AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>
Salthouse E C and Mellhagger D S 1962 The measurement of surface resistivity. In: *Proceedings of the IEE - Part A: Power Engineering*,<br>
pp 41-4<br>
Zhao W, Zhang G an AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1<br>Salthouse E C and McIlhagger D S 1962 The measurement of surface resistivity. In: *Proceedings of the IEE* - *Part A*:<br>Phe 41-4<br>Zhao W, Zhang G and Yan Z 2007 Influence of Trap AUTHOR SUBMITTED MANUSCRIPT - NANO-127285.R1 Page 54 of 54<br>
Salthouse E C and McIlhagger D S 1962 The measurement of surface resistivity. In: *Proceedings of the IEE - Part A*: *Power Engineering*,<br>
pp 41-4<br>
2012 Stationar **Transactions on Dielectrical Insulation, 19** 1732-9<br>**Transactions on Dielectrics and McIllagger D S 1962** The measurement of surface resistivity. In: *P*, pp 41-4<br>**Zhao W, Zhang G and Yan Z 2007** Influence of Trap Paramet Salthouse E C and Mellhagger D S 1962 The measurement of surface resistivity. In: *Proceedings of the IEE - Part A: Power Engineering*, pp 41-4<br>
2hao W, Zhang G and Yan Z 2007 Influence of Trap Parameters of Composite Mate Salthouse E C and McIlhagger D S 1962 The measurement of surface r<br>pp 41-4<br>Zhao W, Zhang G and Yan Z 2007 Influence of Trap Parameters of<br>Voltage Pulses in Vacuum Chinese Society for Electrical Engineering<br>Winter A and Kin Election And Kindersberger J and Lederle C 2008 Surface charge decay on insulators in air and sulfurhexafluorid - Part II: Measurements *IEEE*<br>
107] Winter A and Kindersberger J 2012 Stationary Resistive Field Distribution
	-
	- *Theorem W. Zhang G and Yan Z 2007 Influence of Trap Parameters of Composite Malvidtage Pulses in Vacuum Chinese Society for Electrical Engineering 11-7 (in Chinese Winter A and Kindersberger J 2012 Stationary Resistive Fi*
	-
	-